

# INDEX

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- Abbreviations
  - DEA-related, 599–601
  - DMA-related, 489–491
  - DSC-related, 225–228
  - Micro/nano-TA-related, 647–648
  - TGA-related, 312
  - TMA-related, 380
- Absolute temperature scale, 11
- Accelerating models, 279
- AC dielectric experiments, measuring conditions in, 533–535. *See also* Alternating current entries
- ACR formulation, 368, 369
- Acronyms
  - DEA-related, 602–603
  - DMA-related, 491
  - DSC-related, 228–229
  - related to micro-scale local thermal analysis, 647–648
  - TGA-related, 313
  - TMA-related, 380–381
- Acrylate polymers, 556
  - DMA data for, 462
- Acrylic, highly crosslinked, 439–440
- Acrylonitrile–butadiene (ACN/BD)
  - copolymer, commercial blend with phenolic resin, 306–308
- Acrylonitrile–butadiene–styrene (ABS) terpolymers, 296
- Activation energies, 142, 148–149, 543, 550
  - calculating, 151
  - estimating, 152
  - evaluating, 153
  - measuring, 147
  - of the relaxation process, 510
- Additives
  - low-mass, 269
  - low-molecular-mass, 77
- Adhesion, in dual-coated optical fibers, 371–374
- Adhesive blend, analysis of, 306–308
- Adiabatic calorimetry data, 165
- Adjacent re-entry, 87
- Advanced Thermal Analysis System (ATHAS) Research Group, x
- AFM control software, 640. *See also* Atomic force microscopy (AFM)
- AFM scanning mode, 617
- AFM thermal probe, 628–629
- Agilent HP (Hewlett-Packard) 4284A bridge, 524
- Aging, of glasses, 73
- Aging process, analysis of, 185
- Akinay, Ali E., 319
- Aliphatic polyamides, relaxations of, 571
- $\alpha\beta$  relaxation process, 583
- $\alpha_{\text{CLTE}}$  relation, 591. *See also* Coefficient of linear thermal expansion (CLTE)
- $\alpha_c$  transition, 433
- $\alpha$  dispersion, 18
- $\alpha$ -relaxation curve, 514
- $\alpha$ -relaxation peak, 581

- $\alpha$  relaxations, 415, 512. *See also*  
 Segmental  $\alpha$ -relaxation process  
 amorphous, 433  
 in polyamides, 571  
 in polyurethanes, 565–567  
 $\alpha$ -relaxation signals, 573  
 Alternating-current heating, 630–631. *See also*  
*also* AC dielectric experiments  
 Alternating-current impedance bridges,  
 523  
 Alternating DSC (ADSC), 168. *See also*  
 Differential scanning calorimeters  
 (DSCs)  
 Amine crosslinked epoxy systems, 577  
 Amine-epoxy reaction, 136–137, 148  
 Amine epoxy resin, total water uptake  
 for, 592  
 Amorphous  $\alpha$  relaxation, 433  
 Amorphous polycarbonate, thermal  
 properties of, 165  
 Amorphous polymers  
 first heating-cooling-second heating  
 program for, 213–214  
 glass transition in, 60, 184–187  
 miscibility of, 185–186  
 secondary relaxation processes in,  
 512–514  
 secondary transitions in, 423–424  
 segmental  $\alpha$ -relaxation process in,  
 514–515  
 viscoelastic transitions in, 410–411  
 Amorphous poly(methyl methacrylate),  
 538  
 Amorphous thermoplastics, 388  
 Analyzers, commercially available,  
 596–597  
 Anasys Instruments, 646  
 Annealing  
 in as-received fibers, 121  
 of crystalline polymers, 109–110  
 of glasses, 74–76  
 Annealing peaks, 110  
 Antiplasticization effect, 425  
 Antiplasticized aromatic polymer  
 systems, mechanical property data  
 for, 431  
 Antiplasticizers, 429–430  
 Apolar mainchains, thermoplastics with,  
 556–559  
 ARES rheometers, 523  
 Arrhenius diagrams, analysis of, 551  
 Arrhenius equation, 145, 147, 149, 279  
 fitting shift factors and, 408  
 Arrhenius plots, 291, 510, 511  
 for  $\alpha$  and  $\beta$  transitions, 416  
 construction and analysis of, 549–553  
 of polyurethanes, 567–569  
 Arrhenius rate constant, 154  
 AR Series rheometers, 486  
 As-received fibers, 121  
 As-spun fibers, 120, 432  
 dynamic mechanical curves for, 434,  
 436  
 A stage of cure, 134  
 ASTM E698 kinetics software, 142, 145,  
 151  
 ASTM International Committee E37 on  
 Thermal Measurements, 225, 378  
 ASTM method, 151–152, 287, 293–295  
 ASTM standards,  
 DEA-related, 599  
 DMA-related, 488–489  
 DSC-related, 255  
 TMA-related, 378–379  
 TGA-related, 311–312  
 Atactic nonpolar thermoplastics, 555  
 Atactic PMMA, permittivity and  
 dielectric loss spectra of, 548. *See also*  
*also* Poly(methyl methacrylate)  
 (PMMA)  
 ATHAS databank, 53  
 Athermal nucleation, 85  
 Atmosphere, in TMA experiments, 336  
 Atmospheric pressure chemical  
 ionization (APCI), 250  
 Atomic force microscopes, 616–618,  
 633–634  
 Atomic force microscopy (AFM), 615.  
*See also* AFM entries  
 Atomic polarization, 512  
 Autocatalytic processes, 279, 280  
 Autocatalytic rate equation, 147  
 Autosamplers, 3, 36  
 Autostepwise method/technique, 247,  
 265, 306  
 Autostepwise TGA technique, 276. *See also*  
*also* Thermogravimetric analysis  
 (TGA)

- Autotensioning, 466–467, 469
- AutoZero accessory, 27
- Avrami equation, 88
- Avrami–Erofeev models, 280
- Avrami evaluation, of nonisothermal crystallization of polymers, 92
- Avrami exponent, 89–90
  
- Baffling, in thermobalances, 245
- Bähr Thermoanalyse, 308
- Bair, Harvey E., 7, 241, 319
- Baseline, 54
  - in differential scanning calorimetry, 36
- Baseline method, 95, 96
  - heat of fusion and, 100–102
- BCH-52 liquid crystal standard, 50
- BDS 40 system, 593
- BDS 1200 connection head, 530
- BDS 1200 sample cell, 595
- BDS 1308 parallel-plate shield liquid sample cell, 530
- BDS 2200/2100 RF sample cells, 531
- BDS concept 70 system, 524–525
- Bending modes, 470
- Benzocyclobutene, 296–297
- $\beta^*$  relaxation, 561
- $\beta$  relaxations, 415, 424, 512–514, 560–561, 565
  - dielectric spectra and relaxation frequencies of, 547
  - effect of moisture on, 425–426, 427
  - in polyamides, 571
- Biaxially oriented polypropylene films, analysis of, 642–644
- Biaxially oriented polypropylene, crystallization of, 86–87
- Biaxial orientation, 124
- Biopolymers, application of time-domain reflectometry in, 526
- Bisphenol A polycarbonate, 303
  - TMA curves of, 347
- “Blank” experiments, 244–245
- Blank runs, 54
- Blank TSC, 537–538. *See also* Thermally stimulated current (TSC) technique
- Blends
  - DSC of, 61, 77–80, 186, 202
  - DMA of, 388, 409
  - TGA of, 304–306
  
- Block, 21
- Block temperature, 43
- Boltzmann distribution, 10
- Bose Corporation, 483
- Bose ElectroForce (ELF) DMA Instruments, 483–484
- Bound water, 592
- Bowing, in integrated circuit packages, 374–375
- Bowtie probes, 623
  - resolution of, 624
- Branched polymers, 110
- Brittle fracture, 429
- Broadband dielectric converter (BDC), 522
- B stage of cure, 134
- Bulk chemical reactions, 130
- Bulk properties, in confining environments, 499–500
- “Bulk” sample temperature, 4
- Bulk thermomechanical analysis, 633
- Buoyancy phenomenon, 271
  - in thermogravimetric analysis, 243–244
  
- Cable jacket, orientation recovery in, 370–371
- Cahn Instruments, 225
- Cahn VersaTherm bottom-loading thermogravimetric analyzers, 308–309
- Calculation software products, 215
- Calibrant run, 54
- Calibrants, 465
- Calibration
  - of differential scanning calorimeters, 41–52
  - of dynamic mechanical analyzers, 414, 460–465
  - enthalpy, 50
  - heating, 41–46
  - instrument, 460–465
  - in a micro/nanoscale local thermal analysis experiment, 634–636
  - of thermal lag, 50–52
  - thermocouple, 462–463
  - of thermomechanical analyzers, 332–335
  - of thermogravimetric analyzers, 251–256

- Calibration (*cont'd*)  
 thermogravimetric analysis and,  
 252–256
- Calibration curve, 634
- Calibration samples, 464–465
- Calibration standards, 634–635  
 for fiber measurements, 334–335  
 frequently used, 43–44
- Calorimeter time constants, 25
- Calorimetric purity method, 37
- Calvet DSC, 221. *See also* Differential scanning calorimeters (DSCs)
- Cantilever mode, 466
- Carbon black (CB) analysis, 275–276
- Cationically cured systems, 161
- Cationic photopolymerization, 161–162
- Celcon<sup>®</sup> copolymer, 111
- Cell measuring, in dielectric experiments,  
 528–531
- Chain-folding principle, 87
- Chain mobility, 556
- Chain relaxation capability (CRC),  
 323
- Charge migration, long-range,  
 515–516
- Charge transport, evaluation of, 500
- Charging/discharging currents,  
 isothermal, 520–521
- Chartoff, Richard P., 387
- Chelsea dielectric interface (CDI),  
 522
- Chemical reactions  
 online monitoring of, 500  
 time scale for, 154
- Chiral nematic crystals, 47
- Cholesteric liquid crystals, 47
- Cholesteric phase, 48
- Clausius, R., 14
- Cleaning procedures, in TGA  
 experiments, 258–259
- Clearing point, 47, 48
- Closed loop, 28, 30
- CLTE measurements, 362, 336. *See also*  
 Coefficient of linear thermal  
 expansion (CLTE)
- Coatings, polymeric, 371–374
- Coating thickness, determination of,  
 244–245
- Coaxial-line reflectometry, 524–525
- Coefficient of linear thermal expansion  
 (CLTE), 320, 321, 326, 335, 338, 365.  
*See also*  $\alpha_{CLTE}$  relation; CLTE  
 measurements  
 techniques for measuring, 345
- Coefficient of thermal expansion,  
 conductivity and, 590–591
- Coefficient of volumetric expansion, 321
- Cold crystallization, 84, 188–189, 420, 433  
 isothermal, 92  
 nonisothermal, 92–94
- Cole–Cole plots, 567
- Comb electrodes, 530–531
- Commercial DMA instrumentation,  
 477–488
- Commercial frequency response  
 analyzers, 522
- Commercial instruments  
 special calibration procedures for, 52  
 temperature scale of, 44
- Commercially available analyzers,  
 596–597
- Commercial photocalorimetry  
 accessories, 156
- Commercial thermal analysis  
 instrumentation, 2–3
- Comonomer units, 114
- “Compensation point,” 543
- Compensation rule, 546–547
- Completely amorphous PEEK, 562
- Completely miscible polymer blends, 573
- Complex modulus, 397–399
- Complex permittivity, 504, 520–521
- Complex permittivity data, analysis of,  
 549
- Complex reflection factor, 524
- Complex signals, experimental means for  
 analyzing, 528
- Complex TSC peaks, experimental  
 analysis of, 543
- Complex viscosity, 400
- Compliance calibration, 460
- Composites, 469–472  
 thermoplastic, 375–376  
 TMA of, 363–364
- “Composite” thermal conductivity, 624,  
 625, 627
- Compositional analyses,  
 thermogravimetric, 274–277

- Compression geometry, 459  
 Computerized nomograph, 475  
 Conditioning a sample, in TMA experiments, 339  
 Conductivity  
   coefficient of thermal expansion and, 590–591  
   cure time variation of, 587  
   defined, 586  
   extrinsic, 515  
   variation of, 590  
 Conductivity relaxation (CR), 567  
 Confining environments, information on surface and bulk properties in, 499–500  
 “Consistency” criterion, 473  
 Constant-force mode, 480  
 Constant-frequency experiments, relaxations for, 410  
 Constrained-state DSC measurements, on oriented films, 124. *See also* Differential scanning calorimetry (DSC)  
 Constrained-state measurement, 115–117  
 Contact area, 619  
 Contact mode, 617  
 Contact-mode imaging, 621  
 Contact problems, in dielectric experiments, 532  
 Contact radius, 624–626  
 Continuous-fiber composites, 470  
 Contraction curves, for primary and secondary films, 373, 374  
 Controlled rate thermogravimetric analysis (CRTGA), 246–248, 305. *See also* Thermogravimetric analysis (TGA)  
 Conversion, 137, 138  
   in isothermal TGA experiments, 268  
 Conversion-time curves, 148–149  
 Conversion-time data, 139  
 Conversion-time plots, 280–282  
 Cooling  
   in DSC measurements, 213  
   glass transition on, 64  
 Cooling calibration, 46–50  
 Cooling curves, 72, 74  
 Cooling media, 335–336  
 Cooling rates, 32, 537  
   in a commercial DSC, 163  
   importance in DSC measurements, 214  
   in Perkin-Elmer units, 219–220  
   in TMA experiments, 337–338  
   transforming from DSC into frequencies, 552  
 Cooperative (long-range) processes, dielectric monitoring of, 497  
 Cooperative relaxation signals, 569  
 Copolymers  
   ethylene–vinyl acetate, 304–306  
   glass transition in, 77  
   melting of, 110–115  
 Cox–Merz rule, 401  
 Creep, 325–326, 329  
   measuring, 358–359  
 Creep compliance curves, 361  
 Creep compliance master curve, 359  
 Creep curves, 405  
 Creep–recovery curve, 358  
 Creep testing, 394–395  
 Crimper, 34  
 Crimping, 210  
 Crivello salts, 161  
 Crosslink density, 326  
 Crosslinked polymers, DMA  
   characterization of, 438–456  
 Crosslinking, 344–345  
   effect on glass transition, 77  
   in Nylon 6 fibers, 121  
 Cryostats, 525  
 Cryosystems  
   Novocool, 595  
   Quatro, 593, 595, 598  
 Crystal → crystal transitions, 107–108, 434  
 Crystal growth process, 85–94  
 “Crystalline”  $\alpha_c$  relaxation, 572  
 Crystalline macromolecules, melting of, 96–98  
 Crystalline melting point, 517  
 Crystalline polymers, 388  
   annealing of, 109–110  
   equilibrium melting point of, 17  
   heat of fusion of, 99  
   reporting characteristic data of, 103–104  
   secondary transitions in, 423–424

- Crystalline relaxation, 434
- Crystallinity, 70–71
- $\beta$ -relaxation signal and, 561
  - determination of, 190
  - effect on glass transition temperature, 344, 433–434
  - in measuring  $T_g$ , 417–421
- Crystallinity calculation software, 100
- Crystallizable polymers, 420–421
- Crystallization, 81–94
- induction time of, 89
  - of low-molecular-mass substances, 82–83
  - measured by modulated temperature differential scanning calorimetry, 187–191
  - of polymers, 83–84
  - recording heat effects of, 88
  - stepwise isothermal, 110
  - two-step process of, 94
- Crystallization exotherm, 182
- Crystallization processes, modified method for studying, 188
- Crystallization temperature, 17
- Crystal  $\rightarrow$  nematic transition, 224
- Crystal perfection, 90
- Crystal phase relaxations, 517
- Crystals
- extended-chain, 85–87
  - irradiation of, 162–163
  - reorganization during melting, 104–105
- C stage of cure, 134
- Cure(s). *See also* Curing entries; Time–temperature transformation cure diagram
- changes in dielectric properties during, 585
  - chemical reactions of, 131–132
  - DSC measurements of, 134–136
  - infrared, 274
  - isothermal, 445–450
  - nonisothermal, 450–456
  - stages of, 134
  - $T_g$ -conversion relationship and, 142
  - thermoset, 440–441
  - volatile products from, 271–274
- Cure data, obtaining at low temperatures, 139
- Cured thermosets, transitions in, 450
- Cure exotherm, deconvolution of, 195
- Cure index, 590
- Cure kinetics, 144–154
- defined, 145
- Cure parameters, 133
- DMA techniques for developing, 445–456
- Cure processes
- dielectric characterization and monitoring of, 583–591
  - optimization of, 144
- Cure reaction factors, evaluation by TMA, 357
- Cure reactions
- for applications of TTS kinetics, 148
  - diffusion control of, 153–154
- Cure stages, chemically controlled and diffusion-controlled, 154
- Cure temperature, 442, 450
- reference materials for, 253
- Curing, thermomechanical analysis of, 356–357
- Curing experiments, modulation amplitudes in, 180
- Curing process, characteristics of, 441–445
- Curing system monitoring, MTDSC in, 192–194
- Curved Arrhenius diagrams, 510
- Curve-fitting model functions, 598
- Curve-fitting procedure, 406
- Curve-fitting techniques, 528
- Cutoff temperature, 543
- Cyclic processes, 14
- Cyclic strain, 387
- Cycloaliphatic epoxy, 161–162
- Cytop
- stability of, 300
  - thermal stability of, 298–299
- Cytop compounds, mass loss behavior of, 271
- $d\alpha/dT$  values, 283–284
- Damping peak, 443
- Data acquisition, computer-controlled automated, 534

- DC measurements, dielectric spectrometers for, 598–599. *See also* Direct-current (DC) conductivity
- DEA techniques, 520. *See also* Dielectric analysis (DEA)
- Debye functions, 504, 505
- Debye-type mechanisms, 507–508
- Decelerating models, 279–280
- Decomposition behavior, 305
- Deconvolution procedure, 170, 172–173, 618–619
- Deconvolution program, 630
- Deflection-heating voltage curves, 635
- Degradation, mechanisms in epoxy composites, 591
- Degree of conversion, relationship with ionic conductivity, 589–590
- Degree of cure, 137, 139  
monitoring with penetration measurements, 357
- Degree of swelling, 326, 354–355
- Dehydration, 5
- $\delta$  relaxation, 563–564
- $\Delta T$  correction factor, 49
- Depolarization current density plot, 527
- Depolarization current signals, 569
- DETA accessory, 523–524
- Devitrification, 453, 454, 456  
during nonisothermal cure of epoxy-amine system, 198–199
- DGEBA/DDM + polyethylene oxide (PEO) blends, 583. *See also* Diglycidyl ether of bisphenol A (DGEBA)
- DGEBA epoxy, moisture in, 270
- DGEBA-type epoxies, mixing with multifunctional amines, 578–579
- Diaminodiphenylsulfone (DDS), 135
- Diamond DSC, 219. *See also* Differential scanning calorimeters (DSCs)
- DiBenedetto equation, 142–143
- DICLAD<sup>®</sup> 880 composite, 375–376
- Dielectric, electrical properties of, 503
- Dielectric  $\alpha$ -relaxation band, 519
- Dielectric  $\alpha$  transition shifts, 574
- Dielectric analysis (DEA), ix, 1, 3, 497.  
*See also* DEA techniques  
advantages of, 498  
based on distributed-circuit methods, 524–525  
based on lumped circuit methods, 521–524  
experimental AC techniques for, 594  
how to perform an experiment, 528–538  
of liquid crystalline polymers, 562–565  
for monitoring thermoset cure, 583–585  
of polyamides, 570–572  
of polyesters, 560–562  
of polymer blends, 573–576  
of polyoxides, 559–560  
of polyurethanes, 565–570  
runs with thick PMMA films, 547–553  
standards for, 599  
theory and background of, 502–518  
as a thermal analysis approach, 498–499  
of thermoplastic polymers, 572  
for thermoplastic polyurethane films, 568  
of thermoplastics, 553–576  
of thermosets, 576–592
- Dielectric analyzers, commercially available, 596–597
- Dielectric characterization, of polymers, 501
- Dielectric data, representations of, 505–509
- Dielectric  $\delta$ -relaxation signal, 563–564
- Dielectric depolarization spectroscopy, 526–528
- Dielectric events, impacts of, 586
- Dielectric experiments  
AC, 533  
designing, 585–586  
involving relaxation function, 504  
performing, 528–538
- Dielectric glass transition temperature, 551
- Dielectric increment, 503
- Dielectric induction, 504
- Dielectric instrumentation, 592–599
- Dielectric losses, 506
- Dielectric measurement, 522
- Dielectric measurement systems, high-performance, 593

- Dielectric permittivity, 506
- Dielectric permittivity function, 503
- Dielectric plot structure, inspection of, 518
- Dielectric polymer thick films, 273
- Dielectric probes (labels), 554
- Dielectric relaxation spectroscopy (DRS), 501. *See also* DRS entries
- Dielectric relaxation time, 510–511
- Dielectric reports, 502
- Dielectric research, focus of, 585
- Dielectric response, 505  
of polymeric materials, 512–518
- Dielectric results, complex intensive parameters and, 505–506
- Dielectrics, frequency-dependent response of, 502–505
- Dielectric signatures, of water molecules confined in epoxy resins, 591–592
- Dielectric spectra, comparisons with published literature, 519
- Dielectric spectrometers, 534  
for DC measurements, 598–599  
for measurements in frequency domain, 593–595
- Dielectric spectroscopy, 500  
time-domain, 520–521
- Dielectric spectrum  
decomposition of, 498  
peak assignments in, 518–520
- Dielectric strength, 503
- Dielectric systems, high-precision, 520
- Dielectric techniques, 520–528
- Dielectrometers, 520
- Differential photocalorimetry (DPC), 134, 154–162  
background and principles of, 155–159  
major objective of, 158
- Differential photocalorimetry experiments, 162
- Differential scanning calorimeters (DSCs). *See also* Power compensation DSCs  
calibration of, 41–52  
enthalpy calibration of, 50  
heat capacity calibration of, 50  
temperature calibration of, 41–50  
types of, 36
- Differential scanning calorimetry (DSC), ix, 1, 3, 7–239, 615. *See also* DSC entries; Heat-hold-cool DSC measurements; Modulated temperature DSC (MTDSC); Photo-DSC; Power compensation DSCs; Step scan DSC (SSDSC)  
basics of, 18–36  
calibration on cooling, 48–49  
defined, 18  
elements of thermodynamics in, 9–18  
enthalpy change in, 14  
fast-scan, 162–168  
of fibers, 115–123  
of films, 123–130  
first-order phase transitions in, 16  
heat flux, 21–22  
major applications of, 8  
meanings of, 8  
Mettler Toledo, 25–27  
power compensation, 27–31  
purity determination of low-molecular-mass compounds by, 37–41  
standards for, 225  
usefulness of, 8
- Differential thermal analysis (DTA), 18, 615, 628–629  
thermal resistance in, 19
- Diffusion, time scale of, 154
- Diffusion control, 153–154
- Diffusion-controlled reactions, 198
- Diffusion factor (DF), 193–194
- Diffusion of species, 5
- Diglycidyl ether of bisphenol A (DGEBA), prepolymers, 577. *See also* DGEBA entries
- Dilatometry, 321
- Dillman, Steven H., 387
- Diluents  
effect on  $T_g$  values, 422–423  
sensitivity to, 424
- Dipolar orientation, 586
- Dipolar polymer molecule segments, relaxation of, 583
- Dipole motions, relaxation frequency of, 581
- Dipole processes, 587
- Dipoles, relaxation mechanisms of, 510

- Direct-current (DC) conductivity, 505,  
515, 581. *See also* DC measurements  
Arrhenius plot of, 552
- Dispersion, 503
- Dissipation factor, 506
- Distributed-circuit methods, dielectric  
analysis based on, 524–525
- DMA characterization. *See also*  
Dynamic mechanical analysis  
(DMA)  
calibration, 460–465  
of crosslinked polymers, 438–456  
for thermoplastics, 424–432  
of thermoset cure, 440–441
- DMA/DEA sample configuration, 524.  
*See also* Dielectric analysis (DEA)
- DMA experiments  
modes of operation of, 456–458  
practical aspects of, 456–477
- DMA instrumentation, commercial,  
477–488
- DMA instruments, operating limits of,  
461
- DMA measurements, on fibers and thin  
films, 467–469
- DMA operation, 388
- DMA scan, 402
- DMA sinusoidal stress–strain response  
curves, 396, 399
- DMA solid-mode experiments, 448–450
- DMA standards, 488–489
- DMA systems, categories of, 477–478
- DMA tests, polymer state during,  
389–390
- DMA test samples, 465–472
- DMA  $T_g$  values, 476–477
- $dm/dt$  values, 246, 247
- Doolittle viscosity equation, 323
- Double crystallization, 87
- Double endothermic peak, 191
- Double glass transition, 554
- DPC accessories, 159. *See also*  
Differential photocalorimetry  
(DPC)
- Drawn fibers, 120, 432  
dynamic mechanical curves for, 434,  
436  
melting point of, 116, 117
- Drawn Nylon 6 films, 126, 129
- Draw ratio, 115, 432
- DRS data, 547. *See also* Dielectric  
relaxation spectroscopy (DRS)
- DRS dielectric analysis data, 552
- Drying, of coatings and paints, 272
- DSC-1, 7. *See also* Differential scanning  
calorimeters (DSCs); Differential  
scanning calorimetry (DSC)
- DSC131 line, 220
- DSC 200 F3 Maia, 218
- DSC 204 F1 Phoenix, performance  
characteristics of, 218
- DSC823<sup>c</sup> unit, performance  
characteristics of, 217, 218
- DSC analysis, of thermoplastic  
composite, 375–376
- DSC ASTM E698 methodology, 142
- DSC calibration, in a DSC purity  
determination, 39
- DSC capsules, high-pressure, 35–36, 211
- DSC cell  
covering, 217  
maintaining, 215–216
- DSC curves, 28, 62, 63, 66–67, 69  
annealing and, 74–75  
of Vectran fiber, 123
- DSC data, using, 632
- DSC exotherm, 148
- DSC experiments  
glass transition temperature in, 60–61  
purpose of, 212
- DSC glass transition temperature, 551
- DSC heat flux cell, 21
- DSC heating curves, 72, 70
- DSC heating rate, 165–166
- DSC instrumentation, 9, 217–225  
resolution and precision of, 223–224
- DSC measurements, 208–217  
carrying out, 212–215  
experimental parameters for, 214–215  
hardware considerations related to,  
215–217  
weighing samples for, 224–225
- DSC pans, 34–35, 210–211  
loading samples into, 211–212
- DSC purity determination  
parameters during, 38–39  
simplicity of, 39
- DSC purity technique, examples of, 41

- DSC runs, 155, 156  
 DSC sensor assembly, 23  
 DSC systems, suppliers of, 223  
 DSC temperature scan series, 141  
 DSC  $T_g$  values, 476–477  
 DSC traces, evaluating, 215  
 DTG curve, 260, 272  
 Dual-coated optical fibers, adhesion in, 371–374  
 Dual-cure mechanism, of thermosetting materials, 131  
 Dual/single cantilever geometry, 459  
 Dutch Society for Thermal Analysis (TAWN), 223–224  
 Dynalyser, 487  
 Dynamic dielectric experiments, 567  
 Dynamic DMA scans, 452  
 Dynamic glass transition process, 514  
 Dynamic heterogeneity, in miscible polymer blends, 573–574  
 Dynamic Hi-Res software, 265, 276, 305. *See also* Dynamic rate Hi-Res™ TGA  
 Dynamic mechanical analysis (DMA), ix, 1, 3, 134, 387–495, 498, 615. *See also* DMA entries  
   applications of, 388, 410–424  
   in characterizing viscoelastic materials, 396–399  
   determining shrinkage using, 367–369  
   determining  $T_g$  by, 411–414  
   in developing cure parameters, 445–456  
   finding time to reach gelation using, 443  
   rheology and, 399–401  
   rheology mode in, 445–446  
   in the solids mode, 446–448  
   viscoelastic analysis for, 457–458  
 Dynamic mechanical analyzer, compliance calibration of, 460  
 Dynamic-mode DMA measurements, 367–368  
 Dynamic rate Hi-Res™ TGA, 247. *See also* Dynamic Hi-Res software; Thermogravimetric analysis (TGA)  
 Dynamic viscosity data, 401  
 Dynamic viscosity profiles, 445  
 Eastern Analytical Symposium, 2  
 Edge capacitance, 535  
 Educational programs, in thermal analysis, 1–2  
 Effective crosslink density, 355–356  
 Effective temperature of polarization, 537  
 Eigendeformation calibration, 332  
 Elastic/elasticity modulus, 322, 356, 390  
 Elastic response region, 395  
 Elastic solids, ideal, 390–393  
 Elastomeric modifiers, 583  
 Elastomers, DMA instruments and, 467  
 Electrical effects, nonlinear, 500–501  
 Electrical loss modulus, 506  
 Electric modulus, 506  
 Electrode diameters, measurements of, 535  
 Electrode material, in dielectric experiments, 532–533  
 Electrode polarization, 532, 581  
 Electrode system, parallel-plate, 529–530  
 Electromagnetic fields, undesired, 251  
 Electronic microbalances, 224–225  
 Electronic polarization, 512  
 Electronic thermocouple calibration, errors in, 462–463  
 Electron impact (EI), 249–250  
 Electrostatic disturbances, 251  
 Empirical evaluation, 180–181  
 Endothermic hysteresis peaks, 62, 66–67, 71  
 Endothermic reaction, temperature and, 252  
 Endotherms, 18  
   multiple melting, 110  
 Energy barrier, of  $\alpha$ - and  $\beta$ -relaxation processes in PMMA phases, 550  
 Engineering applications, dielectric characterization of polymers for, 501  
 Engineering strain, 390  
 Enthalpies, 13–14, 94  
   glassy and melt, 63–64  
   of relaxation, 185  
 Enthalpy calibration, of DSCs, 50  
 Entropy, 14  
 Entropy jump, 94

- Environment temperature, 56
- Epoxies, 131  
 high-performance, 135
- Epoxy-amine reaction, 137, 147
- Epoxy-amine systems, 136  
 conversion versus time data for, 140  
 isothermal cure of, 195–197  
 $T_g$ -conversion relationship for, 143  
 vitrification and devitrification during  
 nonisothermal cure of, 198–199
- Epoxy-aromatic diamine systems, 135
- Epoxy resins, dielectric signatures of  
 water molecules confined in,  
 591–592
- Epoxy systems, multicomponent, 199
- Epoxy thermoset, 147
- Equilibrium heat of fusion, 17, 97,  
 98–100
- Equilibrium melting, of polymers, 96–97
- Equilibrium melting point, 82, 97–98,  
 107
- Equilibrium region, 395
- Equilibrium systems, 10
- Equilibrium thermodynamics, 9
- Equipment, micro/nano-TA, 646
- Ethylene copolymers, 111
- Ethylene-propylene copolymers, 111
- Ethylene-vinyl acetate (EVA), two-step  
 decomposition of, 288
- Ethylene-vinyl acetate copolymers,  
 quantitative analysis of, 304–306
- Evolved gas analysis (EGA), 249
- Exothermic heat of reaction, 136–137
- Exothermic hysteresis peaks, 62, 66–67,  
 76
- Exothermic reaction, temperature and,  
 252
- Exotherms, 18  
 asymmetric or multiple-reaction, 152  
 shape of, 136–137
- Expansion behavior  
 of coupled UV coatings, 371–373  
 of polymers, 363
- Expansion measurements, checking  
 performance in, 335
- Expansion-mode TMA, 354–356. *See also*  
 Thermomechanical analysis  
 (TMA)
- Expansion probes, 333
- Experimental AC techniques, for  
 dielectric analysis of polymers,  
 594. *See also* AC dielectric  
 experiments
- Experimental data  
 extrapolation of, 474  
 mathematical analysis of, 519
- Experimental heating rates, 292
- Experimental parameters  
 for DSC measurements, 214–215  
 effects on thermally stimulated current  
 peaks of polymers, 542
- EXSTAR 6000 DSC line, performance  
 characteristics of, 220. *See also*  
 Differential scanning calorimeters  
 (DSCs)
- EXSTAR 6000 Dynamic Mechanical  
 Spectrometer, 483
- Extended-chain (equilibrium) crystals,  
 85–87, 97
- Extended-chain PE crystals, 125. *See also*  
 Polyethylene (PE)
- Extent of conversion, 278
- External thermal resistances, 19
- Extrapolated ending-point of melting,  
 104
- Extrapolated onset temperature, 104  
 of melting, 632
- Extrinsic charges, migration of, 515
- Fahrenheit scale, 11
- Fast DSC rates, 163. *See also*  
 Differential scanning calorimeters  
 (DSCs)
- Fast heating rates, 32
- Fast-reacting thermoset systems, 135
- Fast-scan DSC, 8, 162–168. *See also*  
 Differential scanning calorimeters  
 (DSCs)
- Fast-scan heat flux DSC, 163
- Fast scan mode, 456
- Fast-scan power compensation method,  
 163
- Fast scans, improvement in sensitivity  
 with, 166
- Fast time-domain dielectric spectroscopy,  
 525–526
- Fiber, drawing conditions of, 434. *See also*  
 Fibers

- Fiber crystallinity/orientation, effect on glass transition temperature, 433–434
- Fiber macromolecules, structure of, 115
- Fiber measurements, calibration standards for, 334–335
- Fibers
- characteristics of, 432–438
  - differential scanning calorimetry of, 115–123
  - DMA measurements on, 433, 467–469
  - gel-spun polyethylene, 117–119
  - isotactic polypropylene, 119
  - liquid crystalline polymeric, 121–123
  - polyacrylonitrile, 121
  - TMA of, 363–364
- Fiber samples, running, 215
- Fiber shrinkage, 350
- Field-effect transistors (FETs), 531
- Fillers, in, polymer containing polar groups-572
- Film(s)
- blowing, 433
  - differential scanning calorimetry of, 123–130
  - DMA measurements on, 433
  - liquid crystalline polymer, 128
  - Nylon 6, 126–127
  - oriented, 352, 353
  - polyethylene, 124–126
  - poly(ethylene terephthalate), 126
  - polypropylene, 642–644
  - poly(vinylidene fluoride), 127
  - TMA of, 363–364
  - ultrathin polymer, 637
- Film thickness, 337
- Fingerprinting, 115. *See also* Sample “fingerprint”; TGA “fingerprint”
- First heating–cooling–second heating runs, 212–213
- First law of thermodynamics, 9–10, 67
- First-order phase transitions, 81, 94, 464
- First-order transition, 16
- Fixed-length measurement, 115–117
- Flexible polar sidegroups, 556–557
- Flexural modulus, 391–392
- Flexural probes, 333
- Flexural properties, of polymeric material, 354
- Flexural stress, 326
- Flory–Huggins solvent–polymer interaction parameter ( $\chi$ ), 356
- Flow rate, of purge gas, 34
- Flynn–Wall method, 268, 285, 293, 299
- Folded-chain lamellae, 87, 107
- Force calibration, 332
- Force curves, 351
- Force motors, computerized, 328
- Fourier transform (FT), generating, 174
- Fourier transform infrared (FTIR) spectrometer, 256. *See also* FTIR gas analysis
- Fourier transform infrared spectroscopy, 249
- Fox equation, 78
- Fractional polarization, 528
- Fracture behavior, 428
- Fragility index, 552, 570
- Free enthalpy, 15
- Free-radical systems, UV cure of, 159–160
- Free-to-shrink DSC melting curves, of Nylon 6 films, 129. *See also* Differential scanning calorimetry (DSC)
- Free-to-shrink measurements, 115–117
- Free volume ( $v_f$ )
- estimating, 362
  - measuring, 321–322
- Free-volume approach, 344
- Free-volume dilatation coefficient, 552
- Free-volume theory, 322–324
- Freezing point, 17
- Frequencies, range of, 534–535
- Frequency domain, dielectric spectrometers for measurements in, 593–595
- Frequency effects, 184, 459–460
- Frequency measurements, multiple, 473
- Frequency response analysis (FRA), 521–523
- Fringed micelles, 87
- FRS5 sensor, 27
- FTIR gas analysis, 250. *See also* Fourier transform infrared entries
- Furnace temperatures, 335
- Fusible-link technique, 254–255

- Gallagher, Patrick K., 1, 241
- Gallium, as a melting point standard, 45
- $\gamma$  relaxation, 513, 555, 578, 581  
in oxide polymers, 559–560  
in polyamides, 571
- Gas chromatography–mass spectrometry (GC-MS), 645
- Gases, polymer-evolved, 250
- Gas-switching accessories, 259
- Gaussian functions, 543
- Gelation, 356  
mixing of reactants and, 445
- Gelation curve, 441
- Gelation time, relationship with ionic conductivity, 588–589
- Gel point, 131, 356, 442, 443, 445
- Gel point conversion, 443  
degree of, 444
- Gel-processing technology, for PE films, 126
- Gel-spun fibers, 432  
polyethylene, 117–119
- $T_{g, \text{gel}}$  temperature, 133, 441, 455. *See also* Glass transition temperature ( $T_g$ )
- Gel time, 133, 326
- Geometries, correction factors for, 470
- $G/E$  ratio, 470
- Gibbs free energy, 15
- Gibbs free energy curves, 81–82
- Glasses, physical aging and annealing of, 73–76
- Glass  $\rightarrow$  melt transition, 61
- Glass-reinforced thermoplastic, 377
- Glass–rubber transition, 424  
in linear or high-density polyethylene, 428
- Glass transition, 58–81  
of amorphous polymers, 184–187  
characteristic features of, 415–417  
DSC curve of, 184–185  
effect of crosslink density on, 438–439  
effect of crosslinking on, 77  
effect of low-molecular-mass additives on, 77  
effect of orientation on, 76  
effect of pressure on, 76  
identifying, 411  
measurement techniques for, 65–66  
of nanoprobe-analyzed polymeric materials, 639  
polyblend miscibility and, 77–80  
of a polymer, 69–70  
in polymer blends and copolymers, 77  
in semicrystalline polymers, 68–73  
step scan DSC monitoring of, 205–207  
temperatures necessary to define, 62  
for ultrathin polymer films, 637  
viscoelastic response and, 389
- Glass transition regions  
broad, 564  
overlapping, 195  
stress effects in, 186
- Glass transition signal, 562
- Glass transition temperature ( $T_g$ ), 17–18, 59, 61–68, 133–134, 138, 326, 514. *See also*  $T_{g, \text{gel}}$  temperature;  $T_g$  entries  
assigning for highly crystalline polymers, 418–419  
broadening of, 417, 418  
compositional variation of, 576  
criterion for specifying, 413–414, 439–440  
determining by DMA, 411–414  
factors influencing measurement of, 414–423  
frequency dependence of, 417  
importance of, 59–60  
measurement with modulated temperature DSC, 80–81  
of miscible polymer blends, 78  
molecular mass and, 65, 66  
suppression of relaxation at, 417–418, 419  
in TGA experiments, 263  
in TMA experiments, 338
- Global TSC experiments, measuring conditions in, 536–538. *See also* Thermally stimulated current (TSC) technique
- Global TSC spectrum, features of, 538–540
- Goldstone mode, 565
- Gorbunov, Valeriy V., 615
- Gordon–Taylor equation, 78
- Graft ratios, 80
- Grandy, David, 615

- Haake MARS rheometer, 487–488
- Hamon procedure, 521
- Handbook of Chemistry and Physics*, 335
- Hard-core volume, 321, 322–323, 326
- Hartman equation, 362–363
- Havriliak–Negami function, 514, 543
- Havriliak–Negami model, 505
- Havriliak–Negami parameter estimates, 549
- HDPE fibers, shrinkage of, 352. *See also* High-density polyethylene (HDPE)
- Heat, 11–13  
   defined, 9  
   latent, 13
- Heat capacity, 15–16  
   in the two-phase model of semicrystalline polymers, 71–72
- Heat capacity at constant pressure, 53  
   DSC runs for, 57
- Heat capacity at constant volume, 53
- Heat capacity calibration, of DSCs, 50
- Heat capacity change, evolution in, 200
- Heat capacity determination  
   accuracy of, 56  
   using MTDSC, 192
- Heat capacity increase, 71
- Heat capacity measurement(s), 52–58, 203–204  
   on cooling, 57  
   with modulated temperature DSC, 58  
   software for, 55  
   with traditional DSC, 54–57
- Heat capacity signal, 41, 177, 196, 198  
   excess contribution in, 202–203
- Heat conduction, 12–13
- Heat convection, 13
- Heat-cool-heat protocol, 329
- Heat deflection temperature (HDT), 345, 377
- Heat dissipation, 624, 625, 626, 627  
   theories of, 627
- Heat distortion temperature (HDT), 377.  
   *See also* Heat deflection temperature (HDT)
- Heat flow, 12–13. *See also* Heat flux entries
- Heat flow cycle, 181
- Heat flow equation, four-term, 24–25
- Heat flow modulation, 181
- Heat flow phase angle signal, 195–196
- Heat flow rate, 26, 30
- Heat flow signal, 41  
   terms of, 173
- Heat flux, effect of sample topography on, 619
- Heat flux DSC, 8, 18, 21–22. *See also* Differential scanning calorimetry (DSC); Heat flux DSCs
- Heat flux DSCs, 216. *See also* Differential scanning calorimeters (DSCs)  
   advantage of, 36  
   glass transition in, 59
- Heat-hold-cool DSC measurements, 149.  
   *See also* Differential scanning calorimetry (DSC)
- Heating  
   in DSC measurements, 212–213, 214  
   glass transition on, 64–65
- Heating calibration, 41–46
- Heating experiments, temperature calibration methods in, 334
- Heating program, for thermogravimetric analysis, 260
- Heating rate(s), 27–28, 31–32, 46, 137, 152  
   in a commercial DSC, 163  
   in a DSC purity determination, 38  
   effect of, 461–464  
   effect on indium melting peak height, 164, 165  
   effect on ordinate displacement of DSC signal, 163–165  
   fast, 253, 282, 292  
   influence of, 252  
   in kinetic analyses, 287  
   loss modulus peaks and, 451–452  
   in TMA experiments, 337–338  
   during TSC experiments, 537
- Heating rate methods, multiple, 140–142, 289–290
- Heat leak, 20
- Heat of crystallization, determination of, 91–92
- Heat of fusion, 17, 104, 212  
   determination of, 96  
   of PET film samples, 128
- Heat of fusion calibration, 42, 50

- Heat of reaction, 136–137  
 Heat of transition, 13, 61  
 Heat-only mode, 177  
 Heat-with-some cooling mode, 177  
 Height:width ratio, for a high-purity metal standard, 224  
 Helium, as a purge gas, 33, 157, 167, 172, 219, 220, 241, 252, 289, 328, 336, 364–366, 371–373  
 Helmholtz free energy, 15  
 Hermetically sealed DSC pans, 210–211. *See also* Differential scanning calorimeters (DSCs)  
 Hermetically sealed pans, 35, 58  
 Heterogeneous nucleation, 85, 89  
 High-density polyethylene (HDPE), glass–rubber transition in, 428. *See also* HDPE fibers  
 Higher force tabletop systems, 477  
 High-frequency dielectric data, 535  
 High-frequency (dipolar) dielectric response, changes in, 585  
 High-frequency permittivity, measuring, 525  
 Highly crystalline polymers, 418–420  
 High-pressure dielectric analyzer, 530  
 High-pressure DSC capsules, 35–36. *See also* Differential scanning calorimeters (DSCs)  
 High-purity metals, melting points of, 254  
 High-temperature interfacial polarization modes, analysis of, 499  
 High- $T_g$  phase, vitrification of, 200–201  
 High-thermal-conductivity materials, 627  
 High-thermal-conductivity purge gas, 289  
 Hildebrand's rule, 94  
 Hoffman–Weeks method, 98, 99, 107  
 Homogeneous nucleation, 85, 89  
 Homopolymers, 113–114  
 Hooke's law, 390, 391, 396  
 HP-53 liquid crystal standard, 50  
 HP DSC827° module, 217–218. *See also* Differential scanning calorimeters (DSCs)  
 HSS7 sensor, 27  
 Hybrids, incorporating thermoplastics, 572  
 Hydrogel polymers, 354  
 Hydrogels, mechanical measurements on, 355  
 Hydrogen bonds, modification by moisture sorption, 571  
 Hydrophilic polymers, 269  
 Hygroscopic expansion, 355  
 HyperDSC™, 163. *See also* Differential scanning calorimeters (DSCs)  
 Hysteresis peaks, 62, 66–67, 71, 75–76, 194  
 absence of, 72k  
 intensity of, 184  
*ICTAC Certified Curie Temperature Reference Materials*, 253. *See also* International Confederation of Thermal Analysis and Calorimetry (ICTAC)  
 Ideal elastic solids, 390–393  
 Ideal liquid behavior, 393–394  
 Ideal sample capacitance, 535  
 IDEX series sensors, 531  
 Immiscible blends, interfacial polarization in, 575  
 Impact behavior, 428–432  
 Impedance analysis, 521  
 Impedance analyzers, 523, 595  
 Impedance bridges, alternating-current, 523  
 Incompressible volume, 322–323  
 Indium  
 crystallization of, 83  
 as a melting point standard, 44–45  
 Indium films, 254  
 Industrial applications, of thermomechanical analysis, 363–379  
 Infrared (IR) analysis, 308  
 Infrared cure, 274  
 Infrared microspectrometry, 644. *See also* Near-IR (NIR) spectroscopy; Real-time infrared (RT-IR) spectroscopy  
 Initial rise method, 543  
 Injection-molded GFPPS components, thermomechanical tests on, 378  
 Inorganic compounds, in calibration experiments, 44  
 Instrumental baseline, 36

- Instrumental factors, in measuring  $T_g$ , 414
- Instrumentation. *See also* Instruments  
 DEA, 592–599  
 DMA, 477–488  
 DSC, 217–225  
 Micro/nano-TA, 646  
 thermal analysis, 1, 2–3  
 TGA, 308–311  
 TMA, 326–332
- Instrument baseline, checking, 216
- Instrument calibration, 460–465
- Instrument constant, 50, 56
- Instrument manufacturers, 3
- Instruments. *See also* Instrumentation  
 calibration of, 41  
 drive systems used for, 478  
 turning off, 216
- Instrument Specialists I Series DSC, 217.  
*See also* Differential scanning calorimeters (DSCs)
- Instrument Specialists iSeries TGA, 309.  
*See also* Thermogravimetric analysis (TGA)
- Integral isoconversional methods, 288–289
- Integrated circuit packages, bowing in, 374–375
- “Interchain” effect, 539–540
- Interdigitated electrodes, 530–531
- Interfacial polarization, 515–516, 518
- Interfacial polarization mode, 558
- Intermolecular interaction strength, 574–575
- Internal plasticization effect, 556
- Internal thermal resistance, 19
- International Confederation of Thermal Analysis and Calorimetry (ICTAC), 6, 284. *See also* ICTAC Certified Curie Temperature Reference Materials
- International Temperature Scale, 4
- International Union of Pure and Applied Chemistry (IUPAC), 6
- Interpenetrating polymer networks (IPNs), 576
- Intersection of tangents method, 445
- “Intrachain” effect, 539
- Intrinsic charge carriers, 581
- Intrinsic charges, migration of, 515
- “Introduction to Thermosets,” 131
- Ionic conductivity  
 relationship with degree of conversion, 589–590  
 relationship with gelation time, 588–589  
 relationship with viscosity, 588  
 of thermosetting polymers, 586–587
- Ionic impurities, direct-current conduction of, 583
- Ion mobility, evaluation of, 500
- Ion transport, dynamics of, 521
- Irradiation, baseline shift caused by, 155
- Irradiation curing, 161–162
- Irradiation cycles, repeating, 156
- Irreversible dimensional change, 329
- Irreversible processes, 14
- Irreversible shrinkage, 350
- Isochronal DEA spectra, features of, 547–549. *See also* Dielectric analysis (DEA)
- Isochronal DMA scan, 450. *See also* Dynamic mechanical analysis (DMA)
- Isochronal experiments, 502  
 on amorphous polymers, 423  
 relaxations for, 410
- Isochronal plots, 509, 533
- Isochrone, 475
- Isoconversional analysis, 145
- Isoconversional gelation, 132
- Isoconversional kinetic methods, 140
- Isoconversional methods, 285  
 advances in, 288–289  
 situations encountered when applying, 287–288
- Isoconversional temperature-heating rate data, 152
- Isostructural state, 535
- Isotactic nonpolar thermoplastics, 555
- Isotactic polypropylene fibers, 119
- Isothermal baselines, starting or ending, 214
- Isothermal charging/discharging currents, 520–521
- Isothermal cold crystallization, 92

- Isothermal crystallization, 84  
   DSC recording of, 90  
   measurements of, 216  
 Isothermal crystallization curve, 90  
 Isothermal cures, 445–450  
   conductivity behavior during, 590  
   of epoxy–amine systems, 195–197  
 Isothermal DEA spectra, features of, 547–549. *See also* Dielectric analysis (DEA)  
 Isothermal dielectric frequency scans, 516  
 Isothermal kinetic analysis, 283  
 Isothermal kinetic measurements, 138–140, 146–147  
 Isothermal kinetics, traditional, 145, 146–147  
 Isothermal measurements, 4  
   baseline quality in, 216  
 Isothermal melt crystallization, 88–90  
 Isothermal plots, 502, 509  
 Isothermal polarization temperature, 539  
 Isothermal runs, 155  
   kinetic analyses based on, 280–283  
 Isothermal scans, 502, 547  
 Isothermal stepwise crystallization, 126  
 Isothermal temperatures, in TGA experiments, 262  
 Isothermal TGA, of a phenolic-containing system, 272–273. *See also* Thermogravimetric analysis (TGA)  
 Isothermal TGA experiments, 266–269  
 Isothermal TGA mass loss curves, 267  
 Isothermal time–temperature transformation (TTT) cure diagrams, 441, 444  
 Isotropic film, 124  
 Isotropic phase, 48  
  
 Jade DSC, 219. *See also* Differential scanning calorimeters (DSCs)  
 Jaffe, Michael, 319  
 Johari–Goldstein mode, 513  
 Judovits, Lawrence, 7  
  
 Kalogeras, Ioannis M., 497  
 Kevlar<sup>®</sup>, 121, 123  
  
 Kinetic analyses  
   applications of, 290–295  
   based on a single nonisothermal run, 283–284  
   based on isothermal runs, 280–283  
   based on multiple nonisothermal runs, 284–290  
   lifetime projection and, 299–300  
   objective of, 280  
 Kinetic curves, 280  
 Kinetic data, from isothermal measurements, 236  
 Kinetic free volume fraction, 552  
 Kinetic information  
   continuous, 248  
   importance of, 277  
 Kinetic predictions, 292–295  
 Kinetic rate equation, 193  
 Kinetics, in thermogravimetric analysis, 277–295  
   “Kinetic triplet,” 279, 287, 288  
   evaluating, 283  
 Kinetic viscoelasticity, 451  
 Kissinger method, 284  
  
 Lab environment temperature, 45  
 Lamellar crystals, 107  
 Large sample mass, 259  
 Latent heat, 13  
 Laws of thermodynamics, 9–10  
 L-DTA signal, 631. *See also* Differential thermal analysis (DTA)  
   “Leading edge,” 43, 95, 96  
 Lexan polycarbonate, water permeability of, 303  
 Lifetime estimates, for polymers, 295–301  
 Lifetime predictions, for polymeric materials, 360–361  
 Light guide, 159  
 Light meter, 159  
 Linear amorphous polymers, 388  
   transition region for, 413  
 Linear block copolymers, 565  
 Linear growth rate, of crystals, 85  
 Linear hydrogen-bonded mainchains, polymers with, 565–572  
 Linear isobaric expansivity, 321

- Linear low-density polyethylene (LLDPE), 111
- Linear macromolecules, equilibrium melting point of, 98
- Linear polyethylene, glass–rubber transition in, 428
- Linear stress–strain behavior, 392
- Linear viscoelastic range, 398
- Linear voltage differential transformer (LVDT), 327
- Linseis thermogravimetric analyzers, 309
- Liquid behavior, ideal, 393–394
- Liquid crystalline copolyesters, rigid aromatic, 564
- Liquid crystalline polymer films, 128
- Liquid crystalline polymeric fibers, 121–123
- Liquid crystalline polymers (LCPs)  
dielectric analysis of, 562–565  
ferroelectric properties of, 565  
thermal expansion of, 353–354
- Liquid crystalline standards, 46, 48, 49–50
- Liquid crystals, classes of, 47
- Liquid cylindrical sample cells, 595
- Liquid–liquid transition, in polymers, 557
- Liquid nitrogen, quenching with, 93–94
- Liquid-nitrogen-based cooling system, 223
- Liquid parallel-plate sample cells, 595
- Liquids, dynamic mechanical analysis of, 399–401
- Liquid thermoset samples, 466
- Lissajous figures, 182–183
- “Living” polymerization, 161
- Load-bearing applications, 350
- Local chemical analysis, 644–646
- Local evolved gas analysis (L-EGA), 645
- Local thermal analysis (L-TA), 620, 621, 628–633. *See also* L-TA entries  
overview of, 644–646  
use for, 630
- Lock-in amplifier, 631
- Log plots, 587
- Long-range charge migration,  
mechanisms related to, 515–516
- Loss factor, 582
- Loss factor signal, 577, 579
- Loss modulus, 398, 401  
compliance limits and, 461
- Loss tangent ( $\tan \delta$ ), 398, 399, 476, 506.  
*See also*  $\tan \delta$  entries
- Low-density polyethylene (LDPE),  
102–103, 110, 111  
crystallinity of, 126  
isothermal stepwise crystallization of,  
126  
melting curves of, 109  
in TGA experiments, 263–264
- Low-force tabletop systems, 477
- Low-frequency dielectric data, 535
- Low-frequency dielectric studies, 586
- Low-molecular-mass additives, effect of  
glass transition, 77
- Low-molecular-mass components, 307  
in polymers, 269–271  
purity determination of, 37–41
- Low-molecular-mass substances  
Avrami equation for, 88  
crystallization of, 82–83  
melting of, 94–96
- Low-temperature heat capacity  
measurements, 55
- Low-temperature measurements, 217
- L-TA crater, 641. *See also* Local thermal  
analysis (L-TA)
- L-TA experiments  
components of, 636  
temperature gradients in, 635–636
- L-TA power signal, 631
- L-TMA signal, 631. *See also*  
Thermomechanical analysis  
(TMA)
- Lumped circuit methods, dielectric  
analysis based on, 521–524
- M24 liquid crystal standard, 50
- Machine compliance, errors due to,  
460–461
- Macromolecular systems, impurity  
concentrations in, 37
- Macromolecules, crystallization of, 81
- Macroscopic gelation, versus molecular  
gelation, 131–132
- Magnetic standard, 255
- Mainchain LCPs, 564. *See also* Liquid  
crystalline polymers (LCPs)

- Mainchain segmental motions, dielectric study of, 575
- Mass, 6  
in thermogravimetric analysis, 251
- Mass fraction crystallinity, 99
- Mass loss, 241–242  
in TGA experiments, 262–263
- Mass loss curves, 305–306  
decomposition kinetic analysis of, 299
- Mass loss processes, isothermal experiments for, 266, 267, 269, 271–274
- Mass measurements  
accuracy of, 256  
routine for, 245–246
- Mass spectrometer (MS), 256
- Mass spectroscopy (MS), 249
- Mass standard, 45–46
- Mass-to-charge ratio ( $m/z$ ), 249
- Master cure curves, 145, 149, 150
- Master curves, 361, 404–406  
shifting, 407
- Material characteristics, in measuring  $T_g$ , 417–423
- Material loss factor, 398
- Material properties  
determining key aspects of, 529  
measuring, 339
- Materials  
thermal properties of, 626  
selection of, 428  
viscoelastic, 394
- Mathematical analysis, of experimental data, 519
- Matrix, in polymer blends, 640–642
- Maximum heat-only mode, 178, 179
- Maximum loss modulus, 412
- Maxwell–Wagner–Sillars (MWS)  
polarization, 515–516, 518, 519, 567, 592
- MDSC2920 flow diagram, 175. *See also* Differential scanning calorimeters (DSCs); Modulated DSC (MDSC®)
- MDSC diagram, 176
- Measured capacitance, 535
- Measurement times, high scan rates and, 167
- Measuring systems, with AC bridges, 523
- Mechanical energy input, influence on glass transition, 415
- Mechanical properties, studying using TMA, 355
- Melt crystallization, 58–59, 84  
isothermal, 88–90  
nonisothermal, 91–92
- Melt → crystal transition, 108
- Melt → glass transition, 61
- Melting  
of copolymers, 110–115  
of crystalline macromolecules, 96–98  
in differential scanning calorimetry, 94–115  
of low-molecular-mass substances, 95–96  
recrystallization during, 105  
reorganization and recrystallization during, 190–191
- Melting behavior  
of nanoprobe-analyzed polymeric materials, 639  
of Nylon 6 fibers, 121
- Melting curves, 45, 102, 104–105  
comparative, 40  
of gel-spun polyethylene fibers, 117, 118  
of low-density polyethylene thin film, 127  
of polyethylene films, 125
- Melting peaks, 38, 105, 109–110  
for gel-spun polyethylene fibers, 117–119  
of a low-molecular-mass crystalline substance, 42–43
- Melting point(s), 16–17, 43, 103  
determination of, 340, 343  
for tau lag adjustment, 52
- Melting point lowering, of a low-molecular-mass material, 37
- Melting point standard, 255
- Melting processes, step scan DSC for studying, 207–208
- Melting transition, analysis by MTDSC, 189–190
- Menczel, Joseph D., 1, 7, 319, 387
- Metallized polymers, TSC measurements of, 537
- Metal powders, 44

- Metal standards, 44–45
- Metastable crystals, heating of, 106–107
- Metastable glasses, 73
- Metastable polymeric crystallites, 190–191
- Methacrylate polymers, 556
- Methylenedianiline (MDA), 135
- Mettler Toledo, Inc., 478
- Mettler Toledo DMA SDTA 861, 478–479. *See also* Dynamic mechanical analysis (DMA)
- Mettler Toledo DSC, 25–27, 50–52. *See also* Differential scanning calorimeters (DSCs)
- Mettler Toledo DSC1 unit, 217–218
- Mettler Toledo TGA/DSG1, 309. *See also* Thermogravimetric analysis (TGA)
- MHTC DSC, 221. *See also* Differential scanning calorimeters (DSCs)
- Microanalogs, of traditional thermal analysis techniques, 628–629
- Microbalances, 224–225
- Microdielectrometer sensor, 531
- Micro DSC III/VII, 221. *See also* Differential scanning calorimeters (DSCs)
- Micro-DTA results, 629, 630. *See also* Differential thermal analysis (DTA)
- Micromet Instruments, 531, 593–595
- Micro/nanoscale local thermal analysis, applications of, 637–644. *See also* Micro/nano-thermal analysis ( $\mu/n$ -TA); Microscale thermal analysis; Nanoscale local thermal analysis; Thermal analysis (TA)
- Micro/nanoscale local thermal analysis experiment, 633–636
- Micro/nano-TA equipment, 646. *See also* Micro/nano-thermal analysis ( $\mu/n$ -TA)
- Micro/nano-thermal analysis ( $\mu/n$ -TA), ix, 1, 3, 630. *See also* Micro/nanoscale local thermal analysis entries
- Microscale thermal analysis, 615–649. *See also* Micro/nanoscale local thermal analysis; Micro/nano-thermal analysis ( $\mu/n$ -TA)
- Micro-TMA results, 629, 630. *See also* Thermomechanical analysis (TMA)
- Microwave monitoring techniques, 585–586
- Microwave techniques, 524
- Miniaturized resistive probes, 620
- Miscibility  
in polyblends, 77–80  
relationship with structural similarity and secondary interaction forces, 573–574
- Miscibility gaps, 202
- Miscible blends, intermolecular interaction in, 575
- Miscible interpenetrating polymer networks, 576
- Mixed-mode deformation, 470
- Mobility factor (MF), 154, 193–194
- Model-free kinetics (MFK), 140, 145, 151, 153
- Model-free kinetics software, 142, 151, 153
- Model-free predictions, 294–295
- Modeling, 627
- Modified WLF equation, 591. *See also* Williams–Landel–Ferry (WLF) equation
- Modulated DSC (MDSC<sup>®</sup>), 168, 171. *See also* Differential scanning calorimetry (DSC); MDSC entries; Modulated temperature DSC (MTDSC)
- Modulated heat flow, amplitude of, 58
- Modulated techniques, 5
- Modulated temperature DSC (MTDSC), 8, 134, 133, 161, 168–208, 630. *See also* Differential scanning calorimetry (DSC); MTDSC entries; Temperature-modulated differential scanning calorimetry (TMDSC)
- advantages of, 177, 184
- background and principles of, 168–170
- in characterizing reacting polymer systems, 203
- crystallization measured by, 187–191
- disadvantages associated with, 183
- as an extension of DSC, 183
- heat capacity measurement with, 58

- measurement of glass transition temperature with, 80–81
- Modulated temperature TMA (MTTMA), 329–332. *See also* MTTMA signals; Thermomechanical analysis (TMA)
- Modulated thermogravimetric analysis (MTGA), 248–249. *See also* Thermogravimetric analysis (TGA)
- Modulation amplitude, 178
  - change in, 180
- Modulation cycles, 181
- Modulation frequencies, range of, 180
- Modulation parameters, verification of, 181
- Modulus accuracy, 460
- Modulus–log time curve, 401–402, 404
- Modulus of elasticity, 390–393
- Modulus–temperature curve, 404
- Modulus–temperature data, 434–436, 437
- Modulus values, 472
- Moisture
  - effect on  $T_g$  values, 422–423
  - effects of, 424–428
  - as a plasticizer, 426
- Moisture absorption, effects on polymer relaxation activity, 517–518
- Moisture content, of samples, 339
- Moisture sorption, effect on hydrogen bonds, 571
- Molds, casting, 465–466
- Molecular dipole vectors, orientation of, 512
- Molecular gelation, versus macroscopic gelation, 131–132
- Molecular/ionic species, movements of, 498
- Molecular mass, effect of, 343
- Molecular mobility, dynamics of, 521
- Molecular motions
  - relaxation characteristics of, 556
  - thermal-analysis-related spectroscopic studies of, 563
- Molecular relaxation processes, 387
- Monofilaments, 432
- MTDSC experiments, 105, 169–170, 214–215. *See also* Modulated temperature DSC (MTDSC)
  - modulation selections for, 178
  - sample mass in, 179–180
- MTDSC parameter selection, for thermosets, 180
- MTDSC runs, good, 180–183
- MTDSC terminology, 176–177
- MTTMA signals, 331. *See also* Modulated temperature TMA (MTTMA)
- Multifrequency DEA data, 549
- Multifrequency DMA data, 449, 451
- Multifrequency measurements, 509
- Multiphase polymer blends, 573
- Multiple heating rate, 284
- Multiple heating rate kinetics, 145, 151–153
- Multiple heating rate methods, 140–142, 289–290, 293–295
- Multiple melting endotherms, 110
- Multiple nonisothermal runs, kinetic analyses based on, 284–290
- Multiple-peak melting, of polymers, 107–110
- Multiple reaction exotherms, 152
- Multiple temperature programs, 284
- Multipurpose dielectric systems, 595
- Multistage degradation, 305
- Nanoconfinement effects, dielectric analysis of, 575–576
- Nanoconfinement-induced effects, 499–500
- Nanometer-level accuracy, 617
- Nanophase separation, 570
- Nanoprobe-analyzed polymeric materials, glass transition and melting behavior of, 639
- Nanoprobes, 634
- Nanoscale local thermal analysis, 615. *See also* Microscale thermal analysis
- Near-IR (NIR) spectroscopy, 592. *See also* Infrared entries
- Nematic → isotropic transition, 47, 224
- Nematic liquid crystals, 47
- Nematic phase, 48
- Nematic → smectic transition, 563
- Neoprene rubber, TMA information obtained from, 346
- Network analysis, 524, 525

- Network-forming materials, 130, 131  
 Network-forming polymers, 366  
 Netzsch DMA 242 C, 479–480  
 Netzsch instrumentation, 218  
 Netzsch Instruments, Inc., 479, 531, 593–595  
 Netzsch thermogravimetric analyzers, 309–310  
 Newton's law of cooling, 22  
 Newton's law of viscosity, 393, 397  
 Nitrogen, as a purge gas, 33–34  
 Nomograph  
   computerized, 475  
   time–temperature superposition, 473–476  
 Noncrosslinking side reactions, 588  
 Nonequilibrium melting, of polymers, 100–104  
 Nonequilibrium polymer crystals, free energy of, 82  
 Nonequilibrium thermodynamics, 9  
 Nonisothermal cold crystallization, 92–94  
 Nonisothermal conditions, kinetic measurements performed under, 283–284  
 Nonisothermal cure, 450–456  
   to characterize a thermoset, 194  
   vitrification and devitrification during, 198–199  
 Nonisothermal cure experiments, 180  
 Nonisothermal curves, 283  
 Nonisothermal melt crystallization, 84, 91–92  
 Nonlinear electrical effects, analysis of, 500–501  
 Nonlinear optical effects, analysis of, 500–501  
 Nonmiscible polyblends, 77–78  
 Nonpolar polymers, simple, 554–556  
 Nonpolar thermoplastics, 555  
   dielectric analysis of, 554  
 Nonreversing heat flow, 172, 197  
 Nonreversing signal, 329  
 Nonwoven polymer matrices, 334  
 Normal-mode relaxation process, 515  
 North American Thermal Analysis Society (NATAS), 2  
 North American Thermal Analysis Society Conference, 163  
 Novocontrol Instruments, 524, 530, 531, 593  
 Novocontrol spectrometers, 520  
 Novocontrol TSDC system, 598  
 Novocool cryosystem, 595  
 Novolac, 269, 270  
 Novolac–anhydride system, dynamic mechanical behavior of, 454–456  
 Novotherm system, 595  
*n*th-order kinetics, 138, 146  
 Nucleation, 84–85  
 Nucleation types, Avrami exponent for, 89  
 Numerical differentiation, 284, 286  
 Numerical integration methods, 153  
 Nylon(s), 121  
   dielectric spectra of, 571  
   melting peak of, 122  
   sorption of water by, 424–425  
   water as an antiplasticizer for, 430–432  
 Nylon 6, 571  
 Nylon 6–6, major relaxations in, 424  
 Nylon 6 films, 126–127  
   free-to-shrink DSC melting curves of, 129  
 Nylon 11, relaxation dynamics of, 570–571  
 Nylon 12, 571, 572  
 Nylon M5T, melting curves of, 108  
 Occluded phases, in polymer blends, 640–642  
 Offset, 52  
 Ohm's law, 22  
 One-part thermoset systems, 135  
 Open loop, 28, 30  
 Optical effects, nonlinear, 500–501  
 Optical fibers, dual-coated, 371–374  
 Optical microscopy, 85  
 Optical pyrometry, 4  
 Order–disorder transition, 517  
 Organic crystalline compounds, low-molecular-mass, 37  
 Organic crystals, charge transport and ion mobility in, 500  
 Organic liquids, dielectric measurements of, 530  
 Orientation  
   effect on glass transition, 76

- effect on glass transition temperature, 433–434
- Orientation recovery, in a cable jacket, 370–371
- O-ring leak rate, 302–303
- Oscillating DSC (ODSC), 168. *See also* Differential scanning calorimetry (DSC)
- Oscillator strength, 503
- Oscillatory shear for fluids geometry, 459
- Oven temperature, variations in, 463
- Overlapping phenomena, separating, 195
- Oxidation/oxidative induction time (OIT), 39, 297  
thermogravimetric analysis for, 265
- Oxidative stability, in TGA experiments, 260–265
- Oxygen inhibition, 157
- Ozawa method, 92
- Pan crimping, in a DSC purity determination, 38–39
- Pan masses, 55–56
- Pan type, in a DSC purity determination, 38
- Parallel-plate compression mode, 359
- Parallel-plate dielectric test fixtures, 530
- Parallel-plate electrode system, 529–530
- Partial heating technique, 543, 545
- Particulate contaminants, identification of, 642
- Particulate fillers, polymers containing, 421–422
- Particulate systems, incorporating thermoplastics, 572
- Peak assignments, in dielectric spectrum, 518–520
- Peak cleaning techniques, 540–543
- Peak exotherm temperature, 152
- Peak intensity, dependence on rate of cooling, 537
- Peak temperature, 632  
of melting, 103, 100, 633
- Pendant groups, effect of, 343
- Penetration-mode TMA, 358. *See also* Thermomechanical analysis (TMA)
- Penetration probes, 333
- PEN materials, completely amorphous, 561. *See also* Poly(ethylene-2,6-naphthalate) (PEN); Poly(ethylene naphthalate) (PEN)
- Percolation theory approach, 589
- Perkin-Elmer (PerkinElmer), 225
- Perkin-Elmer DMA7e, 368
- Perkin-Elmer DMA 8000, 480–481
- Perkin-Elmer DPA7 double-beam photocalorimeter accessory, 157
- Perkin-Elmer DSC1 power compensation instrument, 27. *See also* Differential scanning calorimeters (DSCs)
- Perkin-Elmer Hyper<sup>®</sup> DSC, 32. *See also* Differential scanning calorimeters (DSCs)
- Perkin-Elmer Life and Analytical Sciences, 480
- PerkinElmer Life and Analytical Sciences instrumentation, 218–220
- Perkin-Elmer power compensation DSCs, 29, 51. *See also* Differential scanning calorimeters (DSCs)  
glass transition in, 59
- Perkin-Elmer thermogravimetric analyzers, 310
- Permanent set, 359, 395
- Permeability, calculation of, 303
- Permittivity, 503  
frequency dependence of, 547
- Permittivity components, temperature dependence of, 509
- Permittivity data, constructing Arrhenius plots from, 550
- Permittivity plots, 505–506
- PET film, 126. *See also* Poly(ethylene terephthalate) (PET)  
expansion and penetration measurements on, 347
- PET materials, completely amorphous, 561
- PET yarn, storage modulus of, 435
- Phase lag, 179  
changes in, 176  
correction for, 177
- Phase-separated interpenetrating polymer networks, 576

- Phase separation, 200–201  
 indication of, 202–203  
 information on, 569–570  
 reaction-induced, 199–203
- Phase transitions, 16  
 in amorphous and crystalline polymers, 58–115
- Phenolic bonding compound, mass loss from, 272
- Phenolic resin systems, cure of, 278
- Photocalorimetry, differential, 154–162
- Photocalorimetry accessories, 156
- Photochemical reactions, 155  
 correction technique for tracking, 155
- Photodegradation, of polycarbonate, 637–639
- Photo-DSC, 155. *See also* Differential scanning calorimeters (DSCs)
- Photoinitiated free-radical systems, 160
- Photoinitiated polymerization shrinkage, 367–369
- Photoinitiated systems, crosslinking of, 154
- Photooxidation, of polycarbonate, 369–370
- Photopolymerization, cationic, 161–162
- Physical aging process, 406  
 analysis of, 185  
 of glasses, 73
- Physical processes, online monitoring of, 500
- Pigment volume concentration (PVC), 276–277
- Planar sensors, 577
- Plasticization effects, 565
- Plasticizer efficiency, 359–360
- Plasticizers, 77  
 effect on  $T_g$  values, 422–423  
 effects of, 424–428
- Plastic materials, CLTE and  $T_g$  of, 379
- Platelet fillers, 422
- Platinum resistance thermometers (Pt sensors), 27
- PMMA films, thick, 547. *See also* Poly(methyl methacrylate) (PMMA); Thick PMMA films
- Polarization  
 of a dielectric, 512  
 interfacial, 515–516
- Polarization optical microscopy, 85, 98, 100
- Polar mainchain, polymers with, 559–565
- Polar polymers, 427
- Polar sidegroups, 557–559
- Poly(2-hydroxyethyl acrylate) (PHEA), 356
- Poly(2-pentamethylene terephthalamide), equilibrium melting point for, 99
- Poly(3-hydroxybutyrate-co-hydroxyvalerate), melting behavior of, 208
- Polyacrylonitrile (PAN), 110–111
- Polyacrylonitrile fibers, 121
- Polyamides, 121  
 dielectric analysis of, 570–572
- Polyamid-imide polymer, DMA data for, 426–427
- Polyblend grafts, 80
- Polyblends, miscibility in, 77–80
- Polybutadiene-polyisoprene blends, DSC curves of, 78–79
- Poly(butylene terephthalate), nonisothermal crystallization curve of, 91, 92
- Polycarbonate (PC)  
 change of glass transition temperature of, 638  
 photodegradation of, 637–639  
 thermal properties of, 165  
 UV-stabilized, 369–370
- Polyesters, 120–121, 515  
 dielectric analysis of, 560–562  
 flexibility of the mainchains of, 561–562  
 thermotropic mainchain liquid crystalline, 564
- Poly(ether ether ketone) (PEEK), molecular dynamics of, 562
- Polyethylene (PE). *See also* Polyethylenes  
 heat of fusion of, 99  
 hydrophilic sites in, 269  
 LDPE, HDPE, and LLDPE of, 554  
 predicting stability of, 297–298
- Poly(ethylene-2,6-naphthalate) (PEN), 560. *See also* PEN materials

- Poly(ethylene-2,6-naphthalene dicarboxylate) (PEN), 69, 70
- Polyethylene fibers, gel-spun, 117–119
- Polyethylene films, 124–126  
gel-processing technology for, 126
- Poly(ethylene naphthalate) (PEN), 120.  
*See also* PEN materials  
degradation of, 281–282
- Poly(ethylene oxide) (PEO), 559  
reversing component of, 209
- Polyethylenes, crystallization and melting curves of, 112–113
- Poly(ethylene terephthalate) (PET), 97–98, 120, 560. *See also* PET entries  
glass transition of, 72, 75  
glass transition parameters of, 69  
heating curve of, 93  
plasticization of, 186  
preventing crystallization of, 166–167  
quenched, 108  
reversible melting of, 190
- Polyimide precursors, 272
- Polyisobutylene, 555
- Polyisoprene (PI)/poly(vinyl ethylene) (PVE) blends, 574
- Poly(L-lactide) (PLLA), 207
- Polymer blends  
dielectric analysis of, 573–576  
glass transition in, 77  
identifying matrix and occluded phases in, 640–642
- Polymer chain, random scission of, 290
- Polymer characterization, glass transition temperature and, 64
- Polymer composites, charge transport and ion mobility in, 500
- Polymer electrolytes, charge transport and ion mobility in, 500
- Polymer-evolved gases, 250
- Polymer films  
liquid crystalline, 128  
ultrathin, 637  
*Polymer Handbook*, 335, 362
- Polymeric coatings, behavior of, 371–374
- Polymeric crystallites, 104  
types of, 85–88
- Polymeric fibers, liquid crystalline, 121–123
- Polymeric films, 123–130
- Polymeric material(s)  
absorption and desorption of water by, 270  
compositional analyses of, 274–277  
flexural properties of, 354  
key processes in, 323  
nanoprobe-analyzed, 639  
origin of dielectric response of, 512–518  
service performance of, 360–361  
thermal expansion of, 345
- Polymeric stabilizer systems, studying, 297
- Polymerization, free-radical, 159–160
- Polymerization shrinkage, photoinitiated, 367–369
- Polymer Laboratories, 520
- Polymer melting  
characteristic temperatures of, 103  
time-dependent processes during, 104–106
- Polymer networks, interpenetrating, 576
- Polymer oxidation products, 293
- Polymer–polymer interactions, 356
- Polymer–polymer miscibility, 186  
determining, 78–80
- Polymer properties, free volume and, 322
- Polymer relaxation activity, effects of moisture absorption on, 517–518
- Polymers. *See also* Amorphous polymers; Semicrystalline polymers  
analyzing dielectric spectra of, 538–553  
characteristic parameters of, 362–363  
compositional heterogeneity of, 369–370  
configuration/dynamic properties/  
applications relationships in, 499  
containing particulate fillers, 421–422  
cooling rate for, 32  
crystallization of, 83–84  
degradation mechanisms of, 261  
dielectric analysis of, 594  
dielectric characterization of, 501  
equilibrium melting of, 96–97  
equilibrium melting points of, 97–98, 111  
fabricated, 319  
with flexible polar sidegroups attached to an apolar mainchain, 556–557

Polymers (*cont'd*)

- fracture behavior of, 428
- glass transition temperatures for, 68
- heat capacity of, 53–54
- investigating the stability of, 296–297
- lifetime estimates for, 295–301
- with linear hydrogen-bonded mainchains, 565–572
- liquid–liquid transition in, 557
- low-molecular-mass components in, 269–271
- mass loss of, 241–242
- measuring mechanical properties of, 387
- melting points of, 114
- melting transition of, 632
- miscibility of, 185–186
- multiple-peak melting of, 107–110
- network-forming, 131
- nonequilibrium melting of, 100–104
- overlapping transitions in, 170–171
- PAN, 110–111
- peak assignments in dielectric spectrum of, 518–520
- with polar mainchain, 559–565
- with polar sidegroups, rigidly attached to an apolar mainchain, 557–559
- propensity for change of, 162
- structural weaknesses in, 296
- thermal analysis of, ix, 1
- thermal conductivities of, 463
- thermal degradation of, 290
- two-phase model of, 69
- unzipping of, 261
- use of, 65
- viscosity of, 393
- Polymer structure–property characterization, 388
- Polymer structures, thermoplastic, 560–562
- Polymer thermal stability, in TGA experiments, 260–265
- Polymer thick films (PTF), 272
  - composition and cure of, 273
  - cure of, 259
- Poly(methyl methacrylate) (PMMA). *See also* Atactic PMMA; PMMA films; Thick PMMA films
  - DRS and TSC data of, 549
  - measurements on, 538–553
  - partial heating technique in, 545
- Poly(*n*-alkyl methacrylates), 557
- Polyoxides, dielectric analysis of, 559–560
- Polyoxymethylene (POM), 559
- Polyphenylene sulfide, glass-filled, 377–378. *See also* Poly(*p*-phenylene sulfide)
- Poly(phenylene terephthalamide) (PPT), 121. *See also* Kevlar<sup>®</sup>
- Poly(*p*-phenylene sulfide), melting curves for, 188
- Polypropylene, 555
  - crystallization of, 86–87
- Polypropylene fibers, isotactic, 119
- Polypropylene films, biaxially oriented, 642–644
- Poly(propylene oxide) (PPO), 559
- Polystyrene (PS), change of glass transition temperature of, 638
- Polystyrene (PS)/PVME blends, 574
- Poly(tetrafluoroethylene) (PTFE), 97, 130, 375, 376
  - intensity of glass transition in, 418
  - relaxation activity in, 555
- Polyurethanes, dielectric analysis of, 565–570
- Poly(vinyl acetate) (PVAc), 269
- Poly(vinyl alcohol) (PVA) fibers, 434
  - storage modulus of, 437
- Poly(vinyl chloride) (PVC), 77
  - degradation of, 261
  - plasticized, 359, 360
  - relaxations of, 558
  - stabilizing additives for, 263
- Poly(vinylidene fluoride) (PVDF)
  - melting of, 191
  - relaxations of, 558
- Poly(vinylidene fluoride) crystallites, reorganization of, 192
- Poly(vinylidene fluoride) films, 127
- Poly(vinyl methyl ether) (PVME)
  - degradation of, 297
  - oxidative thermal degradation of, 263
  - thermal and thermooxidative stability of, 267–268
  - thermooxidative degradation of, 259, 269, 292

- Position calibration, 335  
 in thermomechanical analysis, 332
- Postcure, 444
- Postmelting baseline, 36, 100, 102
- Power compensation DSCs, 8, 27–31, 159, 163, 204–205. *See also* Differential scanning calorimeters (DSCs); Differential scanning calorimetry (DSC)  
 advantage of, 36  
 burn off procedure for, 216–215  
 operation schematic of, 29
- Power compensation sample holder, 28
- Power-law models, 279
- Precision difference method, 526
- Predictions  
 for long time periods, 405–406  
 model-free, 294–295  
 TTS-based, 409
- Preload force, 466
- Premelting baseline, 36, 100, 102
- Prepolyimide resin, 366
- Pressure  
 crystallization control and, 530  
 effect on glass transition, 76
- Pressure DSC, 8, 217–218. *See also* Differential scanning calorimetry (DSC)
- Pressure-sensitive tape, 130
- Pretension, 349, 468–469
- Pretensioning, 467
- Prigogine, I., 9
- Primary nucleation, 84
- Primary nuclei, 84
- Prime, R. Bruce, 1, 7, 241, 319
- Principle of energy conservation, 9–10
- Probe heat loss “jump,” 626–627
- Probe normal force, 622
- Probe power consumption, measurement of, 628–629
- Probes  
 design of, 621  
 penetration depth of, 636  
 spatial resolution of, 622  
 types of, 329  
 weight of, 335
- Probe selection, in a micro/nanoscale local thermal analysis experiment, 634
- Probe tip, 621  
 geometry of, 622
- Program temperature, 43
- Projected results, confidence in, 300
- Proton NMR spectroscopy, 592
- Published literature, comparisons of dielectric spectra with, 519
- Pultrusion processes, 149  
 time-temperature profile for, 150
- Pultrusion systems, 135
- Purge gas(es), 4, 22, 33–34, 336  
 dry, 212  
 flow rate of, 57  
 temperature calibration and, 46  
 thermal conductivity of, 252  
 in TMA measurements, 328
- Purge gas options, in TGA experiments, 259–260
- Purity determination, of low-molecular-mass compounds, 37–41
- Purity software, 38
- PVME/poly(2-chlorostyrene) (P2CS) blends, 574–575
- Q Series DSCs, 221–223. *See also* Differential scanning calorimeters (DSCs)  
 controlled cooling rates for, 223
- Q Series modules, 23–25, 176
- Quasi-isothermal analysis, 190
- Quasi-isothermal experiments, 178–179
- Quasi-isothermal mode, heat capacity measurement with modulated temperature DSC in, 58
- Quasi-isothermal modulation, 177, 182
- Quatro cryosystem, 593, 595, 598
- Quenching methods, 93–94
- Quick Freeze Deep Etch (QFDE), 94
- Rabinowitch model, 154
- Radiofrequency (RF) dielectric measurements, 531
- Radiofrequency impedance analyzers, 524, 525
- Raman microspectrometry, 644
- Ramp rate(s), 4, 6, 204, 207–208  
 modulation of, 181
- Random chain scission, 261

- Random copolymers, 111–114  
melting equation of, 114
- Rate constant, 282
- Rate equation, in the single-step process, 278–279
- Rate of conversion, 137, 138–139  
measuring, 146
- Rate of photoinitiation, 160
- Reaction heat capacity, 196
- Reaction-induced phase separation (RIPS), 199–203
- Reaction-induced vitrification, 198–199
- Reaction order models, 279–280, 281
- Reaction rate, conversion dependence of, 279
- Reaction temperature, in cationically cured systems, 161
- Reactive systems, MTDSC for monitoring, 192–194
- Reading, Mike, 7, 615
- Real-time infrared (RT-IR) spectroscopy, 159. *See also* Infrared entries
- Recorded dielectric plot structure, inspection of, 518
- Recording, of well-resolved thermal transitions, 528
- Recovery region, 395
- Recrystallization, 181  
during melting, 105, 190–191
- Reduced-frequency nomograph, 474–475
- Reference calorimeter, 30
- Reference disk thermocouple, 24
- Reference holder, 31
- Reference materials, for thermogravimetric analysis, 251–256
- Relaxation, normal-mode, 515. *See also*  $\alpha$ -relaxation entries;  $\beta$  relaxations;  $\delta$  relaxation;  $\gamma$  relaxation; Relaxation behavior; Relaxations; Secondary relaxation entries; Stress relaxation entries
- Relaxation activity, effects of moisture absorption on, 517–518
- Relaxation behavior  
generalizations about types of, 423  
subglassy, 562
- Relaxation dynamics, 497–498  
of thermoplastic polymers, 572
- Relaxation frequencies, 512, 551
- Relaxation function, dielectric experiments involving, 504
- Relaxation map(s)  
evaluation of, 598  
of temperature dependencies, 579–578
- Relaxation map analysis (RMA), 528
- Relaxation mechanisms, dielectric strength of, 540
- Relaxation processes, in semicrystalline polymers, 423–424
- Relaxation rates, in miscible blends, 575
- Relaxations, 410–411  
crystal phase, 517  
dielectric strength of, 544  
of polyethylene, 554–555  
of polyoxides, 559–560  
in semicrystalline polymers, 516–517  
of the TSC spectrum, 539
- Relaxation spectrum, damping mechanisms affecting, 422
- Relaxation temperatures, dependence on absorbed water level, 425
- Relaxation time, 510–511  
“Relaxed” permittivity, 503
- REOLOGICA Instruments, Inc. US, 486
- Reorganization, during melting, 190–191
- Reorientational dynamics, in LCPs, 563
- Resolution, increasing, 171  
“Reversible” expansion/contraction, 355
- Reversible melting, 95
- Reversible processes, 5, 9, 14
- Reversing heat capacity, 171–172
- Reversing heat flow, 170, 171–172
- Reversing signal, 329
- Rheological properties, at gelation, 443
- Rheology  
dynamic mechanical analysis and, 399–401  
measurements of, 387
- Rheology mode, in dynamic mechanical analysis, 445–446
- Rheometers, rotational, 486–488
- Richard’s rule, 94
- Riga, Alan, 241
- Rigaku TG/DTA 8120 system, 310. *See also* Differential thermal analysis (DTA)
- Rigid amorphous fraction, 71
- Rigid amorphous phase, 346, 516

- Rigid pendant groups, effect of, 344
- Roe–air–Gieniewski (RBG) method, 297–298
- Room temperature permittivity plots, 592
- Rotational diffusion, 547
- Rotational rheometers, 477–478, 486–488
- RSA-III rheometers, 523
- RT Instruments, Inc., 310, 482
- Rubber products, compositional analysis of, 276
- “Rubbery flow,” 389
- Run parameters, 4–5  
for thermoplastics, 177–179
- Sample(s)  
applying initial load to, 339–340  
encapsulating, 34–36  
interaction with atmosphere, 5  
irregularly shaped, 337  
size and geometry of, 259  
thermal history of, 339
- Sample calorimeter, 30
- Sample cell, 595
- Sample cycling technique, 364
- Sample dimensions, control of, 529
- Sample environment, in dielectric experiments, 532
- Sample “fingerprint,” 212. *See also* Fingerprinting
- Sample geometry modes, clamping errors and, 469–470
- Sample holder, 31  
coolant of, 46  
maintaining, 215–216
- Sample impedance, 523, 524
- Sample mass, 4, 179–180  
in a DSC experiment, 33  
in DSC measurements, 211  
large, 259  
in TGA experiments, 257–259
- Sample pans, TGA, 257, 258
- Sample platform, 326, 328
- Sample preparation  
in dielectric experiments, 528–531  
for differential scanning calorimetry, 210–211  
in a micro/nanoscale local thermal analysis experiment, 633–634  
thermoset data and, 134–135  
in TMA experiments, 338–339
- Sample probes, 326–327, 328  
TMA, 332
- Sample requirements, in TMA experiments, 336–337
- Sample run, 54
- Sample size, in a DSC purity determination, 38–39
- Sample strain, 461
- Sample temperature, 82, 463–464  
deviations in, 289
- Sample test geometries, 458–459
- Sample thermocouple, 24  
calibration of, 464–465
- Sample thickness, measurements of, 535
- Santonox R, 39
- Sapphire run, 54
- Sartorius, 225
- Scanning force microscopy (SFM), 615
- Scanning probe microscopes, 616
- Scanning rates, in TMA experiments, 337–338
- Scanning thermal microscopy (S<sub>Th</sub>M), 618–620
- Scanning tunneling microscopy (STM), 616
- Scientific instrumentation, evolution of, 3
- “Seating” process, 372–373
- Secondary crystallization, 90
- Secondary-ion mass spectrometry (SIMS), 644
- Secondary nucleation, 84
- Secondary relaxation(s), 577. *See also* Relaxation entries  
importance of, 429
- Secondary relaxation dynamics, 574
- Secondary relaxation loss peak, 429
- Secondary relaxation processes, in amorphous polymers, 512–514
- Secondary transitions, 410  
in amorphous and crystalline polymers, 423–424
- Second law of thermodynamics, 10, 11
- Second-order transitions, 16, 433
- Segmental  $\alpha$ -relaxation process, in amorphous polymers, 514–515
- Segmental relaxation mode, 516
- Segmented polyurethanes, 565

- Seiko EXSTAR6000 TGA/DTA series, 310. *See also* Differential thermal analysis (DTA); Thermogravimetric analysis (TGA)
- Seiko Instruments, 220, 482
- Self-nucleation, 85
- Semiconductors, charge transport and ion mobility in, 500
- Semicrystalline miscible polymer blends, 575
- Semicrystalline PEEK, 562
- Semicrystalline polycarbonate, thermal properties of, 165. *See also* Polycarbonate (PC)
- Semicrystalline polymers  
 $\alpha$  relaxation in, 514  
 glass transition in, 68–73  
 melting range in, 16  
 relaxation processes for, 410, 423–424, 516–517  
 softening point for, 346  
 transitions in, 60  
 melting of, 100
- Sensors  
 crosstalk between, 20  
 implantable, 531
- Sensys DSC line, 220–221. *See also* Differential scanning calorimeters (DSCs)
- Service performance, of polymeric materials, 360–361
- Setaram DSC instrumentation, 220–221
- Setaram Instruments, 598
- Setaram thermogravimetric analyzers, 310
- Shear deformation, 470–471
- Shear modulus, 326
- “Shear sandwich” experiment, 450
- Shear sandwich geometry, 459
- Shear strain, 391
- Shear stress, 391, 393
- Shift factor, 407
- Shimadzu instrumentation, 221
- Shimadzu TGA-50/50H, 310–311. *See also* Thermogravimetric analysis (TGA)
- Shrinkage, 349–350  
 of fibers and thin films, 469  
 photoinitiated, 367–369  
 predicting, 369  
 thermal cure, 366–367
- Shrinkage force, 350–351
- Sidechain LCPs, 563. *See also* Liquid crystalline polymers (LCPs)
- Sidegroups  
 elimination of, 261  
 flexible polar, 556–557  
 polar, 557–559
- Sigma-Aldrich, 334
- Sigmoidal baseline, 100–102
- Silicone gel, heating in nitrogen, 300–301
- Silicon nanopropes, 622, 624
- Simple nonpolar polymers, 554–556
- Single glass transition criterion, applicability of, 575
- Single heating rate methods, 284, 293
- Single isotherm mode, 456
- Single-relaxation-time mechanism, 507
- Single-relaxation-time model, 504
- Sinusoidal strain, 396, 397
- Slow heating rates, 32
- Slow time-domain dielectric experiments, 598
- Slow time-domain dielectric spectroscopy, 520–521
- Slow time-domain measurements, 536
- Small-molecule reactions, Rabinowitch model for, 154
- Small sample mass, 630
- Smectic  $\rightarrow$  isotropic transition, 563
- Smectic liquid crystals, 47
- Smectic phase, 48
- Softening point, 412  
 determining, 345–346  
 and heat deflection temperature, 326
- “Softening” temperature, 629
- “Soft” mode, 565
- Software issues, 3
- Software products, 8–9
- Sol fraction, 442
- Solid-mode experiments, 448–450
- Solids, ideal elastic, 390–393
- Solid  $\rightarrow$  solid transition, 130
- Solvent removal, 5
- Spatial resolution, 620–624  
 of thermal nanopropes, 639–640
- Specific heat capacity, 15, 53

- Spectrometers, 506  
 dielectric, 593–595
- Spherulites, 88
- Standard DSC pans, 34–35. *See also*  
 Differential scanning calorimeters  
 (DSCs)
- Standards, DMA-related, 488–489
- Starting point of melting, 103
- Static force, 466
- Static-mode technique, 367
- Static stress, 468
- Static stress–strain measurements, 469
- Stationarity, 180
- Steady state, 180, 182–183
- Step heating technique, 543
- Step isothermal experiments, 509
- Stepped isotherm mode, 456, 457
- Step scan DSC (SSDSC), 168–169, 204–  
 205. *See also* Differential scanning  
 calorimeters (DSCs)
- Stepwise isothermal approach, 247
- Stepwise isothermal crystallization, 110
- Stereochemistry, influence on glass  
 transition temperature, 344–345
- Stoichiometrically balanced reaction,  
 147
- Storage kinetics, 144
- Storage modulus, 398, 401  
 compliance limits and, 461  
 frequency-dependent increase in, 450  
 during gelation, 443
- Storage modulus–cure time plot, 447
- Straight (linear) baseline, 100–102
- Strain rate, 393, 397
- “Strength” parameter, 570
- Stress effects, in the glass transition  
 region, 186
- Stress relaxation, 326, 395
- Stress-relaxation behavior, 359
- Stress relaxation curves, 405
- Stress–strain behavior, 392
- Stress–strain curves, 348–349
- Strongly asymmetric blends, 576
- Structural fingerprinting, 115. *See also*  
 Fingerprinting
- Structure formation, online monitoring  
 of, 500
- Styrene–acrylonitrile copolymer, DSC  
 heating curves of, 79–80
- Subambient sample thermocouple  
 calibrations, 464–465
- Submicrometer spatial resolution,  
 623–624
- Submilligram samples, 158
- Substrate effect, 336
- Subsurface imaging, scanning thermal  
 microscopy for, 618
- Sub- $T_g$  relaxations, 423. *See also* Glass  
 transition temperature ( $T_g$ )
- Superheating, 98, 102, 106, 117
- Supermolecular structures, 88
- Surface properties, in confining  
 environments, 499–500
- Surfaces, thermal probing of, 627–628
- Swelling  
 kinetics of, 354  
 measuring using expansion-mode  
 TMA, 354–356
- Swelling ratio, 354
- Swier, Steven, 7
- Swollen systems, parameters for, 355–356
- Symbols  
 DEA-related, 559–601  
 DMA-related, 489–491  
 DSC-related, 225–228  
 Micro/nano-TA-related, 647  
 TGA-related, 312  
 TMA-related, 380
- Système International de Unités (SI), 9
- $T^*$  (magnitude of intermolecular  
 interactions), estimating, 362
- TA 2970 system, 593
- TAI 2900 DSC modules, 176. *See also*  
 Differential scanning calorimeters  
 (DSCs); TA Instruments entries  
 temperature modulation for, 174
- TAI modules, 22–25  
 910, 2910, and 2920 modules, 22–23  
 MDSC phase-corrected signal  
 comparison for, 177
- Q Series modules, 23–25
- TA Instruments, Inc. (TAI), 221–223,  
 311, 481, 486, 520, 523
- TA Instruments Q800 DMA, 481–482
- Tan  $\delta$  function, 506. *See also* Loss  
 tangent (tan  $\delta$ )
- Tan  $\delta$  peak, 412, 413

- Tau lag, 50, 52
- TAWN. *See* Dutch Society for Thermal Analysis (TAWN)
- Temperature
- of the  $\alpha$  relaxation, 18
  - crystallization, 17
  - in differential scanning calorimetry, 10–11
  - of half-unfreezing, 60
  - molecular fractionation by, 274–275
  - in thermal analysis, 4
  - in thermally activated processes, 277–278
  - in thermogravimetric analysis, 251–256
- Temperature accuracy, kinetic data and, 256–257
- Temperature axis calibration approaches, 253–255
- Temperature calibration
- of differential scanning calorimeters, 41–50
  - of dynamic mechanical analyzers, 461–464
  - in a micro/nanoscale local thermal analysis experiment, 634–636
  - of thermogravimetric analyzers, 251–256
  - in thermomechanical analysis, 332
  - in a TMA instrument, 334–335
- Temperature calibration graph, 632
- Temperature Calibration of Thermomechanical Analyzers*, 334
- Temperature dependence, in step reaction thermosets versus photoinitiated free-radical polymerization, 160
- Temperature gradients, 19
- in L-TA experiments, 635–636
- Temperature-induced phase separation, 202
- Temperature integral approximation, 284
- Temperature measurements, accuracy of, 256, 461–464
- Temperature-modulated differential scanning calorimetry (TMDSC), 169. *See also* Differential scanning calorimetry (DSC); Modulated temperature DSC (MTDSC)
- Temperature ramp, 628
- Temperature scales, 11
- Temperature scans, 402–403, 509
- Temperature sensor, 252
- Temperature shift factor, 407
- Temperature step increments, 457
- Temperature–time/frequency analysis, 473–477
- Temperature values, 11
- display of, 104
- Tenacity, 432
- Tensile mode, problems with, 466
- Tensile-mode TMA study, 370–371. *See also* Thermomechanical analysis (TMA)
- Tensile modulus, 322, 390
- Tensile properties, measuring by thermomechanical analysis, 348–354
- Tensile storage modulus, of polymeric films, 436–438
- Tensile storage modulus curves, 437
- Tensile stress–strain plot, 392
- Tension geometry, 459
- Tension mode, thermomechanical analysis in, 349, 350
- Tension-mode experiments, 340
- Tension probes, 333
- Tertiary nucleation, 84
- Test frequency, in measuring  $T_g$ , 415–417
- Testing material quality, in dielectric experiments, 533
- Testing modes, for DMA test samples, 466
- Test samples, DMA, 465–472
- Tetraglycidylmethylenedianiline (TGMDA), 135
- $T_g$ . *See* Glass transition temperature ( $T_g$ )
- $T_{g0}$  temperature, 133, 441–442
- $T_{g\infty}$  temperature, 133, 441, 442
- TGA curve, 260. *See also* Thermogravimetric analysis (TGA)
- TGA/DSC, 4, 250, 254. *See also* Differential scanning calorimetry (DSC)
- TGA/DTA, 4, 250, 254, 255. *See also* Differential thermal analysis (DTA)
- TGA experiments
- choices associated with, 257
  - designing and performing, 256–260

- extent of reaction during, 266
  - isothermal, 266–269
  - objectives of, 256–257
  - pros and cons of, 301
- TGA “fingerprint,” 308. *See also* Fingerprinting
- TGA/FTIR, 4. *See also* Fourier transform infrared (FTIR) spectroscopy
- TGA instruments
  - heating rates of, 289
  - temperature calibration of, 255
- TGA kinetic analysis, confidence in projected results of, 300
- TGA kinetics software, 285
- TGA/MS, 4. *See also* Mass spectroscopy (MS)
- TGA multiple heating rate methodology, 305
- TGA runs, heating rates used for, 292
- TGA sample pans, 257, 258
- TGA vaporization studies, 369–370
- TGA/WVT capsule technique, 302–304. *See also* Water vapor transport (WVT)
- $T_g$ -conversion relationship, 138, 197, 198, 514
  - vitrication and, 142–144
- $T_g$ -degree of cure relationship, 440–441
- $T_g$  measurement, thermomechanical analysis in, 340–343
- $T_g$  relaxations, measuring in crystallizable polymers, 420–421
- $T_g$ -time data, 144
- $T_g$  values, DMA and DSC, 476–477
- Thermal analysis (TA)
  - in combinations, 4
  - educational programs for, 1–2
  - of fibers, 115–123
  - general methods and techniques of, 2
  - micro- and nanoscale local, 615–649
  - studies in, 2
  - uses for, 1
- Thermal analysis experiment, micro/nanoscale local, 633–636
- Thermal analysis measurements, 1
  - goal of, 115
- Thermal analysis techniques
  - for measuring, 1
  - underlying principles of, ix
- Thermal analysis vendors,
  - DEA instruments, 592–599
  - DMA instruments, 477–488
  - DSC instruments, 217–225
  - Micro/nano-TA instruments, 646
  - TGA instruments, 308–311
  - TMA instruments, 347
- Thermal Characterization of Polymeric Materials* (Turi), x
- Thermal conductivity, 20, 30, 203–204, 624–628
  - behavior of materials with, 627
  - images via, 618, 619–620
  - of purge gases, 252
- Thermal contact, 289
- Thermal cure shrinkage, 366–367
- Thermal decomposition, 247
- Thermal degradation, 293
  - initiation at weak link sites, 290
- Thermal degradation kinetics, predicting, 287
- Thermal diffusivity, 19, 203
- Thermal environment, rapidly changing, 5
- Thermal equilibrium, 12
- Thermal events, timescale of, 180
- Thermal expansion
  - determining the coefficient of, 340
  - of polymeric materials, 345
  - measurements of, 320
- Thermal force–distance curves, 624–628
- Thermal gradients, 464
- Thermal history, reproducible, 32
- Thermal lag, 19, 20, 21, 337
  - calibration of, 50–52
- Thermal lag constant, 51–52
- Thermally activated processes, rate of, 277–278
- Thermally stimulated current (TSC), 517. *See also* TSC entries
- Thermally stimulated current analysis, of thick PMMA films, 538–547
- Thermally stimulated current peaks of polymers, effects of experimental parameters on, 542
- Thermally stimulated current technique, 501, 526–528, 540
  - advantages of, 528

- Thermal nanoprobes
  - spatial resolution of, 639–640
  - temperature calibration for, 635
- Thermal nucleation, 85
- Thermal probes
  - design of, 620–624
  - heating of, 632–633
- Thermal probe temperature, calibration of, 631–633
- Thermal radiation, 13
- Thermal resistance, 19–20, 25
- Thermal sampling (TS), 528, 543, 546
- Thermal scan mode, 456–457
- Thermal scanning rates, 465
- Thermal scans, 162
- Thermal shrinkage, 350
- Thermal stability
  - estimating, 292
  - in inert and oxidizing atmospheres, 296–297
  - lifetime estimates and, 295–301
- Thermal transitions, sensitive recording of, 528
- Thermobalance(s)
  - commercial, 244
  - in thermogravimetric analysis, 242–243
- Thermobalance components, thermal expansion of, 245
- Thermocouple calibration, errors in, 462–463
- Thermocouples, 4, 18, 22, 289, 328
  - in DMA instruments, 461–462
- Thermodilatometry (TD), 320. *See also* Thermomechanical analysis (TMA)
- Thermodynamic  $C_p$ , 205
- Thermodynamic parameters, change of, 94
- Thermodynamics
  - goal of, 9
  - laws of, 9–10
- Thermodynamic temperature scale, 11
- ThermoFisher Scientific Materials Characterization, 487
- Thermogravimetric analysis (TGA), ix, 1, 3, 241–317. *See also* TGA entries; Thermogravimetry (TG)
  - applications of, 295–308
  - background principles and measurement modes of, 242–250
  - benefits of, 276–277
  - calibration and reference materials for, 251–256
  - controlled rate, 246–248
  - of copolymers, 304–306
  - factors affecting, 243–246
  - information from, 250
  - instrumentation for, 308–311
  - kinetics in, 277–295
  - measurements and analyses in, 256–277
  - for measuring percent solids and pigment volume concentration, 276–277
  - modulated, 248–249
  - temperature axis calibration approaches in, 253–255
- Thermogravimetric compositional analyses, 274–277
- Thermogravimetry (TG), 241. *See also* Thermogravimetric analysis (TGA) standards for, 311–312
- Thermomagnetometry (TM)
  - temperature axis calibration method, 253
- Thermomechanical analysis (TMA), ix, 1, 3, 319–386, 615. *See also* TMA entries
  - expansion-mode, 354–356
  - of films, fibers, and composites, 363–364
  - of glass-reinforced thermoplastic, 377–379
  - industrial applications of, 363–379
  - instrumentation for, 326–332
  - key applications of, 340–363
  - in measuring softening point, 345–346
  - measuring tensile properties by, 348–354
  - modulated-temperature, 329–332
  - physical quantities measured by, 325–326
  - principles and theory of, 320–326
  - shrinkage information from, 366–367
  - standards for, 378–379
  - of thermoplastic composite, 376

- for thin bonded film measurements, 364–365
- Thermometers, 11
  - platinum resistance, 4
- Thermooxidative degradation, 263
- Thermooxidative stability, 264–265
- Thermopiles, 26
- Thermoplastic composite, 375–376
- Thermoplastic polymers, 583
  - structures of, 560–562
- Thermoplastics
  - with apolar mainchains and polar sidegroups, 556–559
  - dielectric analysis of, 553–576
  - DMA characterization for, 424–432
  - glass-reinforced, 377–379
  - hybrids and particulate systems incorporating, 572
  - run parameters for, 177–179
- Thermoplastic samples, 466
- Thermoplastic/thermoset adhesive, yield from, 266
- Thermoset coatings, ambient cure conditions of, 194
- Thermoset cure
  - chemical reactions of, 131–132
  - extent of, 440–441
  - model-free kinetics for, 153
- Thermoset cure processes, 193
  - temperatures in, 149
- Thermosets, 130–154, 438
  - dielectric analysis of, 576–592
  - handling and processing of, 134
  - MTDSC parameter selection for, 180
  - nonisothermal cure to characterize, 194
  - partially cured, 140
  - samples of, 472
  - uncured, 131
  - use of MDSC for, 194–203
  - versus thermoplastic polymers, 131
- Thermosetting systems, 135
  - heat of reaction of, 136
- Thermospatial resolution, 622
- Thermotropic LCPs, 563. *See also* Liquid crystalline polymers (LCPs)
- Theta Industries, 311
- Thick-film screen process, 26
- Thick PMMA films. *See also* Poly(methyl methacrylate) (PMMA)
  - DEA runs with, 547–553
  - thermally stimulated current analysis of, 538–547
- Thin bonded films, measurements on, 364–365
- Thin-film (chip) calorimetry, 163
- Thin films
  - characteristics of, 432–438
  - DMA measurements on, 467–469
  - dynamic mechanical analysis data for, 436–438
- 4,4'-Thiobis(3-methyl-6-tert-butylphenol)
  - determination of purity of, 39
- Third law of thermodynamics, 10
- Thomson–Gibbs equation, 98, 99, 107, 114–115
- Three-point bending, 391
- Three-point bending geometry, 459
- Three-point bending mode, 466
- Time, for describing dielectric phenomena, 503–504
- Time constants, calorimeter, 25
- Time-dependent discharge current, 536
- Time-dependent phenomena/processes, 5–6
  - during polymer melting, 104–106
- Time-dependent stress relaxation modulus, 395–396
- Time-domain dielectric spectroscopy
  - fast, 525–526
  - slow, 520–521
- Time-domain reflectometry (TDR), 525–526
- Timescale, in TSC experiments, 527
- Time–temperature equivalence principle, 402, 404, 409
- Time–temperature–frequency relationship, 401–409
- Time–temperature superposition (TTS), 409
  - modified, 406–407
- Time–temperature superposition kinetics, 145, 148–150
- Time–temperature–superposition master curves, 275, 362, 404
- Time–temperature superposition nomograph, 473–476

- Time-temperature superposition  
 principle, 359, 361, 398, 403-409, 421, 511  
 significance of, 409
- Time-temperature superposition  
 software, 473
- Time-temperature transformation cure  
 diagram, 441-456
- Time-temperature-transformation (TTT)  
 diagram, 197
- Time to steady state, 21
- TMA curves, 321, 322. *See also*  
 Thermomechanical analysis  
 (TMA)  
 interpretation of, 364  
 in machine and transverse directions,  
 352-353
- TMA experiments  
 applying initial load to sample in,  
 339-340  
 performing, 335-340  
 preparations for, 335-336
- TMA instruments, 330  
 calibration of, 332-335  
 expansion response of, 335  
 vertical-design, 327-328
- TMA penetration measurements, 360
- TMA probes/applications, 333
- TMA sample cell, 336
- TMA shrinkage measurements, 369
- TMA specifications, 330
- Top-bottom (T-B) signal, 617
- TOPEM<sup>®</sup>, 168  
 software, 27  
 technique, 174-175
- Topographic artifacts, 619
- Torsional (shear) mode, 466
- Torsional shear geometry, 459
- Torsion pendulum technique, 417
- Total heat flow, 170
- Toughness, 348-349
- Traditional amorphous fraction, 71
- Traditional amorphous phase, glass  
 transition of, 71
- Traditional DSC, measurement of heat  
 capacity with, 54-57. *See also*  
 Differential scanning calorimetry  
 (DSC)
- Training, thermal analysis, 2
- Transition region, 395  
 for linear amorphous polymers,  
 413
- Transition temperature, 253
- Triclinic → hexagonal transition, 130
- Trouton's rule, 94
- True differential heat flow, 31
- True reference temperature, 30
- TSC experiments, global, 536-538. *See*  
*also* Thermally stimulated current  
 entries
- TSC peaks, complex, 543-547
- TSC spectra, 565, 566  
 analysis of, 538  
 global, 538-540
- TS scans, 543
- Tsukruk, Vladimir V., 615
- Turi, Edith, x
- Turnkey dielectric/impedance  
 spectrometers, 593
- Twisted nematic crystals, 47
- Two-part thermoset systems, 135
- Type A/B/C polymers, 512
- Tzero calibration, 52
- Tzero cell design, 222
- Tzero modes, 192
- Tzero sensor temperature, 43
- Tzero technology, 23, 24
- Tzero thermocouple, 24
- Ultrathin films, dielectric methods for,  
 500
- Ultrathin polymer films, glass transitions  
 for, 637
- Ultraviolet (UV) radiation. *See* UV  
 entries
- Unconstrained measurement, 115-117
- Uncured thermosets, 131
- Underlying heating rates, 178-179
- Underlying rate, 168
- Undrawn Nylon 6 films, 126, 129
- Uniaxial orientation, 124
- Unidirectional composites, 470, 471
- Uniform temperature distribution, 20
- Universal values, 361
- "Universal" WLF equation, 407
- Unoriented films, DSC experiments on,  
 124
- "Unrelaxed" permittivity, 503

- UV (ultraviolet)-curable materials, 154–155
- UV cure, of free-radical systems, 159–160
- UV exposure cycles, multiple, 162
- UV irradiation, 157
- UV-stabilized polycarbonate, 369–370
- van't Hoff calorimetric purity method, 39
- van't Hoff equation, 37
- van't Hoff plot, 38, 39
- Variable-amplitude phase generator, 523
- Variable-heating-rate experiments, 123
- Vassilikou-Dova, Aglaia, 497
- Vectra<sup>®</sup>, 121–123
- Vectra group, relaxations of, 564
- Vectran<sup>®</sup>, 123
- Vectran film, 128
  - as-extruded, 129
  - stress-strain curves of, 353
- Vectran liquid crystalline film, tensile storage modulus of, 436, 438
- Veeco, 646
- Vendors
  - commercial DMA instrumentation, 477–488
  - DMA instruments from, 483–485
  - thermal analysis, 478–483
- Vesta system, 646
- VICAT softening point, 345
- Vinyl monomer-containing polymer (VACR), 368, 369
- Viscoelastic behavior, characterization of, 394–401
- Viscoelastic characterization, 390
- Viscoelastic damping devices, 476
- Viscoelastic data, time-temperature superposition of, 473
- Viscoelasticity, 324, 357, 360
  - of polymers, 319–320
- Viscoelastic materials, 394
- Viscoelastic transitions, 410–411
- Viscosity
  - measuring, 444
  - Newton's law of, 393, 397
  - relationship with ionic conductivity, 588
- Vitrification, 132–134, 149, 153, 442, 453, 454
  - absence of, 455
  - of a high- $T_g$  phase, 200–201
  - during nonisothermal cure of epoxy-amine system, 198–199
  - $T_g$ -conversion relationship and, 144
- Vitrification curve, S-shaped, 441
- Vitrification time, 448
- Vogel-Tammann-Fulcher-Hesse (VTFH) equation, 511, 551
- Vogel-Tammann-Fulcher-Hesse relaxation time function, 519, 533
- Vogel temperature, 511
- Volatile cure products, 266
- Volatile products. *See also* Volatiles
  - condensation of, 245
  - in TGA experiments, 261–262
- Volatile reaction products, loss of, 271–274
- Volatiles
  - containment of, 135–136
  - loss of, 158
- Volume change, on melting, 94
- Vyazovkin, Sergey, 241
- “Waiting time,” 534
- Warping, in integrated circuit packages, 374–375
- Water
  - as an antiplasticizer for nylon, 430–432
  - as a melting point standard, 44
  - permeability of, 302–304
- Water absorption, real-time dielectric measurements of, 592
- Water molecules, dielectric signatures of, 591–592
- Water-polymer interactions, 356
- Water vapor transport (WVT), 301–304
- Water vapor transport capsule, 302
- Well-resolved thermal transitions, sensitive recording of, 528
- Wide-angle X-ray diffraction (WAXD), 99
- Williams-Landel-Ferry (WLF) equation, 323–324, 407–408, 510–511. *See also* Modified WLF equation; WLF entries

- Windowing polarization (WP), 528
- Winter method, 443
- WinTSC program, 598
- Wire mesh method/technique, 443–444, 449
- WLF parameters, 510–511. *See also* Williams–Landel–Ferry (WLF) equation
- WLF relationships, nonlinear, 417
- WLF shift factor curve, 408
- Wollaston probes, 646
  - geometry of, 623
- Wollaston Wire probe, 620–621, 622
  - thermospatial resolution expected from, 623
- Wunderlich, Bernhard, x
- Wunderlich’s rule, 61
- X-ray photoelectron spectrometry (XPS), 644
- m*-Xylylene diamine-cured DGEBA, 583
- Yarns, 432
- Young’s modulus, 322, 326, 390
  - measuring by thermomechanical analysis, 348
- z*-axis feedback, 636
- Zero-entropy-production melting, 82, 106–107
- Zero-entropy-production melting points, 98, 102, 107
- Zero heating rate, 41
- 01dB-Metravib Instruments, 484–485
- Zeroth law of thermodynamics, 9, 10–11
- Zone drawing–zone annealing method, 433
- “Zoom” imaging facility, 640